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## Design Example Report

<b>Title</b>	<b><i>275 W PFC Front End Using HiperPFS™-4 PFS7727H</i></b>
<b>Specification</b>	90 VAC – 264 VAC Input; 385 VDC Output
<b>Application</b>	PFC Front-End
<b>Author</b>	Applications Engineering Department
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### **Summary and Features**

- Highly integrated, low component count, low-cost PFC
- Ultra-low reverse recovery loss diode (Qspeed™)
- Power Integrations eSIP-16 low-profile controller package
- “Cool-Pad” package reduces IC mounting hardware
  - Eliminates insulating pad/heat-spreader
- EN61000-3-2 Class-D compliant
- High PFC efficiency enables up to 80+ Platinum PC Main design
- Enhanced light load power factor (PF)
  - PF >0.9 at 20% load and 230 VAC, 50 Hz input
  - PF >0.95 at 50% load
- Frequency sliding maintains high efficiency across load range
  - >95% from 10 to 100% load (115 VAC and 230 VAC input)
- Feed forward line sense gain – maintains relatively constant loop gain over entire operating voltage range
- Excellent transient load response
- Frequency adjusted over input line voltage and load
  - Spread-spectrum across >60 kHz window simplifies EMI filtering requirements
- Integrated Qspeed switching diode reduces component count and simplifies assembly

### **PATENT INFORMATION**

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**Important Note:**

All testing should be performed using an isolation transformer to provide the AC input to the prototype board.



## 1 Introduction

This report describes a PFC power supply utilizing a HiperPFS-4 PFS7727H PFC controller with integrated power MOSFET and switching diode. This power supply is intended as a general purpose platform that operates from universal input line voltage and provides a regulated 385 V DC output voltage and continuous output power of 275 W.

The DER-720 power supply is designed to operate with forced air cooling greater than 200 LFM for all input and load conditions up to the rated maximum ambient temperature of 50 °C.

This document contains the power supply specification, schematic, bill of materials, inductor documentation, printed circuit layout, and performance data.

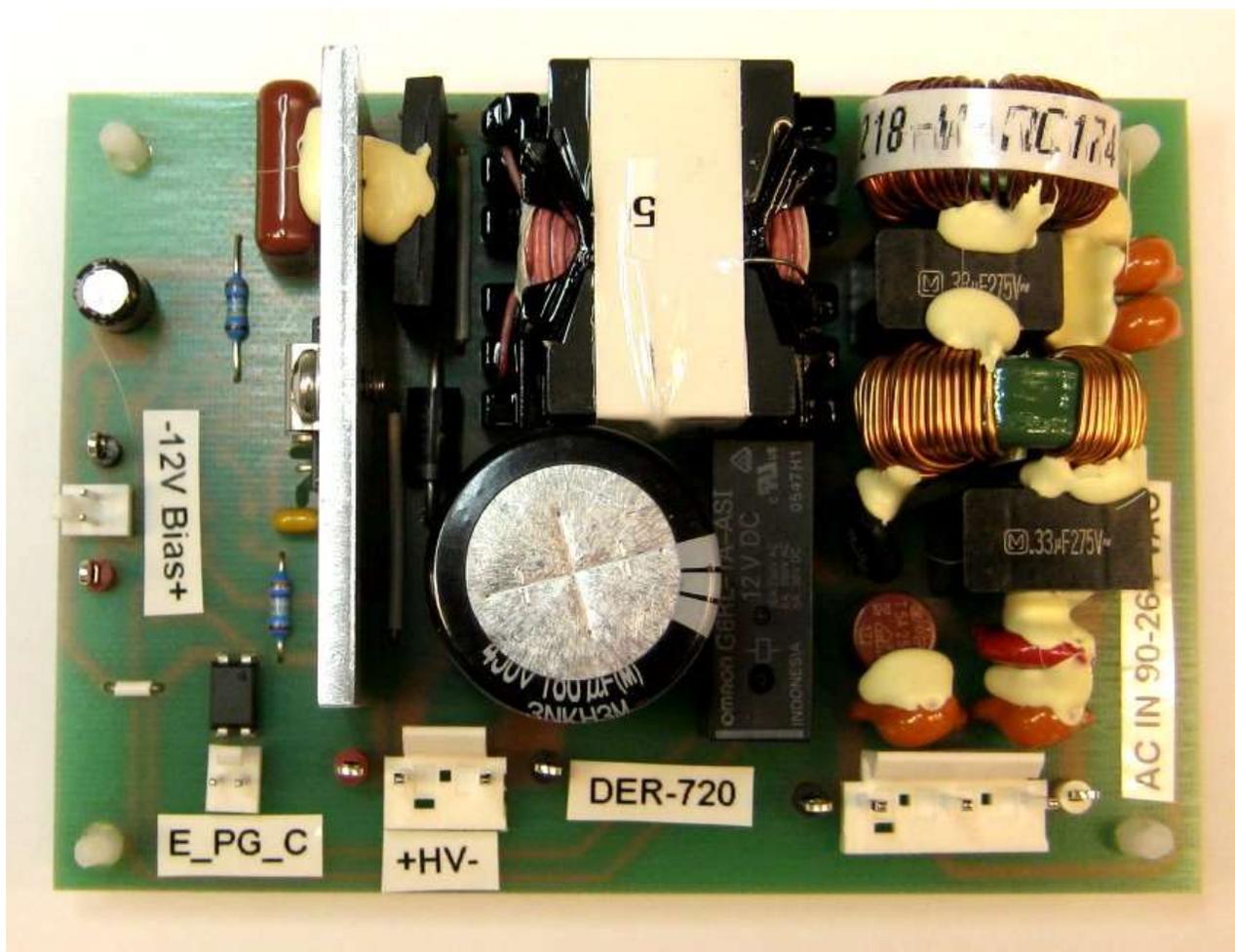


Figure 1 – Populated Circuit Board Photograph (Top View).



**Figure 2** – Populated Circuit Board Photograph (Back View).

## 2 Power Supply Specification

The table below represents the minimum acceptable performance of the design. Actual performance is listed in the results section.

Description	Symbol	Min	Typ	Max	Units	Comment
<b>Input</b>						
Voltage	$V_{IN}$	90		264	VAC	3 Wire.
Frequency	$f_{LINE}$	47	50/60	64	Hz	
<b>Output</b>						
Output Voltage	$V_{OUT}$	375	385	395	V	20 MHz Bandwidth.
Output Ripple Voltage p-p	$V_{RIPPLE}$			30	V	
Output Current	$I_{OUT}$		0.71		A	
<b>Total Output Power</b>						
Continuous Output Power	$P_{OUT}$		275		W	Forced air cooling
<b>Efficiency</b>						
Full Load	$\eta$	94			%	Measured at $P_{OUT}$ 25 °C.
Minimum efficiency at 20, 50 and 100 % of $P_{OUT}$	$\eta_{80+}$	94			%	Measured at 115 VAC Input.
<b>Environmental</b>						
Line Surge						1.2/50 $\mu$ s surge, IEC1000-4-5, Series Impedance: Differential Mode: 2 $\Omega$ . Common Mode: 12 $\Omega$ .
Differential Mode (L1-L2)			2		kV	
Common mode (L1/L2-PE)			3		kV	
Ambient Temperature	$T_{AMB}$	0		50	°C	Forced convection required. 300 LFM Min.
<b>Auxiliary Supply Input</b>						
Auxiliary Supply	$V_{aux}$	15		17	V	DC Supply.

### 3 Schematic

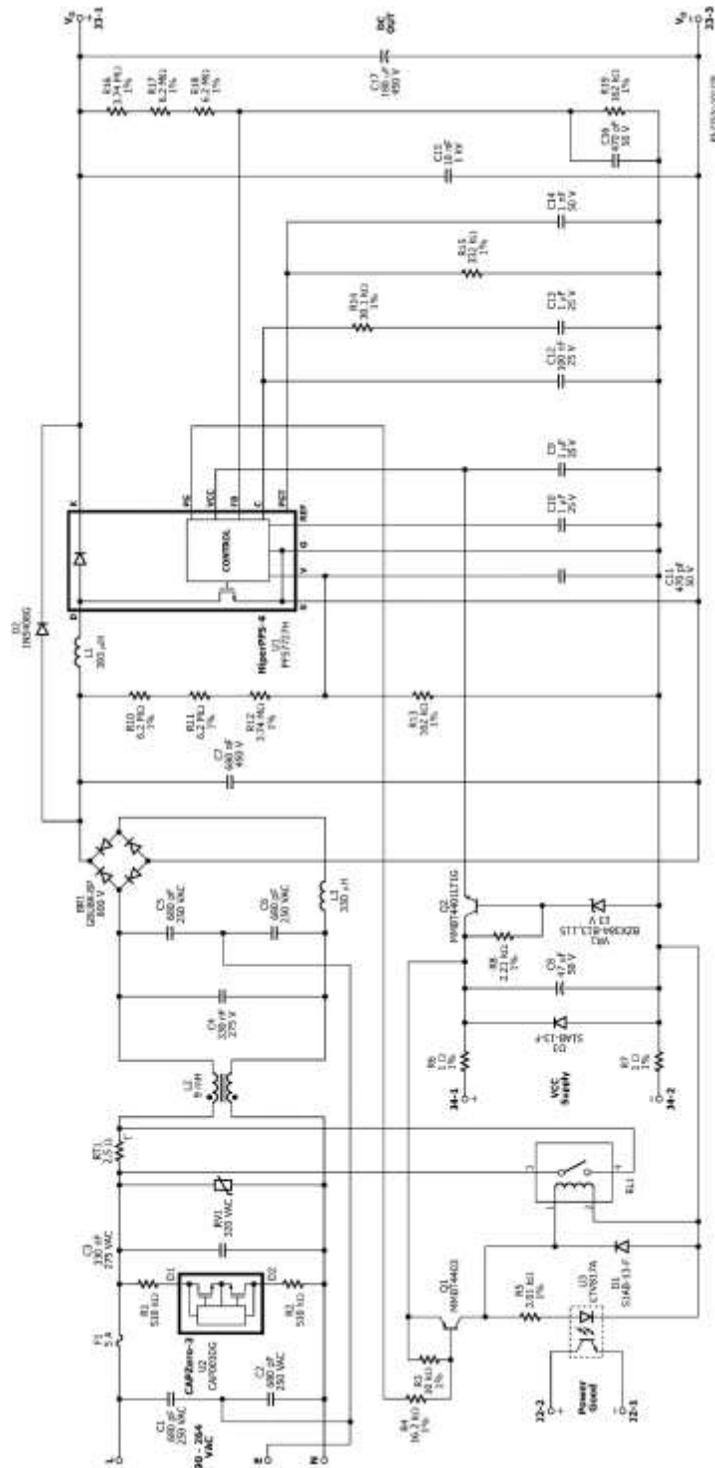


Figure 3 – Schematic.



## 4 Circuit Description

This PFC circuit is designed around the Power Integrations PFS7727H integrated PFC controller. This design is rated for a continuous output power of 275 W and provides a regulated output voltage of 385 VDC nominal, maintaining a high input power factor and overall efficiency over line and load, while remaining low in cost.

### 4.1 *Input EMI Filter and Rectifier*

Fuse F1 provides overcurrent protection to the circuit and isolates it from the AC supply in the event of a fault. Diode bridge BR1 rectifies the AC input. Capacitors C1, C2, C3, C4, C5 and C6 in conjunction with inductors L2 and L3, constitute the EMI filter for attenuating both common mode and differential mode conducted noise. Film capacitor C7 provides input decoupling charge storage to reduce input ripple current at the switching frequencies and harmonics.

Resistors R1, R2 and CAPZero™-3 IC U2 are provided to discharge the EMI filter capacitors after line voltage has been removed from the circuit, while dissipating zero power during operation.

Metal oxide varistor (MOV) RV1 protects the circuit during line surge events by effectively clamping the input voltage seen by the power supply.

### 4.2 *PFS7727H Boost Converter*

The boost converter stage consists of the boost inductor L1 and the PFS7727H IC U1. This converter stage operates as a PFC boost converter, thereby maintaining a sinusoidal input current to the power supply while regulating the output DC voltage.

During start-up, diode D2 provides an inrush current path to the output capacitor C17, bypassing the switching inductor L1 and switch U1 in order to prevent a resonant interaction between the switching inductor and output capacitor.

NTC thermistor RT1 limits inrush current of the supply when line voltage is first applied. Thermistor RT1 is bypassed by the electro-mechanical relay RL1 after the output voltage is in regulation and a power good signal from U1 is asserted low. Resistor R3, R4, and Q1 drive relay RL1 and optocoupler U3. Diode D1 clamps the relay coil reverse voltage during de-assertion transitions Resistor R5 limits the current to the diode in the optocoupler. IC U3 provides optocoupler isolation through connector J2 for a POWER GOOD output signal if required.

Capacitor C15 provide a short, high-frequency return path to RTN for improved EMI results and to reduce U1 MOSFET drain voltage overshoot during turn-off. Capacitor C9 decouples and bypasses the U1 VCC pin.



Resistor R15 programs the output voltage level [via the POWER GOOD THRESHOLD (PGT) pin] below which the POWER GOOD (PG) pin will go into a high-impedance state.

Capacitor C10 on the REF pin of U1 is a noise decoupler for the internal reference and also programs the output power for either full mode, 100% of rated power [C10 = 1  $\mu$ F] or efficiency mode, 80% [C10 = 0.1  $\mu$ F] of rated power.

#### 4.3 ***Input Feed Forward Sense Circuit***

The input voltage of the power supply is sensed by the IC U1 using resistors R10, R11, R12 and R13. The capacitor C11 bypasses the V pin on IC U1.

#### 4.4 ***Output Feedback***

An output voltage resistive divider network consisting of resistors R16, R17, R18, and R20 provide a scaled voltage proportional to the output voltage as feedback to the controller IC U11 setting the PFC output at 385 V. Capacitor C16 decouples the U1 FB pin.

Resistor R14 and capacitor C13 provide the control loop dominant pole. C12, attenuates high-frequency noise.

#### 4.5 ***Bias Supply Series Regulator***

The PFS7727H IC requires a regulated  $V_{CC}$  supply of 12 V nominal for operation, with an absolute maximum voltage rating of 15 V.  $V_{CC}$  levels in excess of this maximum could result in failure of the IC. Resistor R8, Zener diode VR1, and transistor Q2 form a series regulator that regulates the supply voltage to IC U1 to 12.4 V nominal. Capacitor C9 decouples the input auxiliary supply voltage to ensure reliable operation of IC U1.

Resistors R6, R7 and capacitor C8 provide filtering of the external  $V_{CC}$  voltage source. Reverse polarity protection of this source is achieved with diode D3.

The +15 V auxiliary supply is applied on connector J4.

### 5 PCB Layout

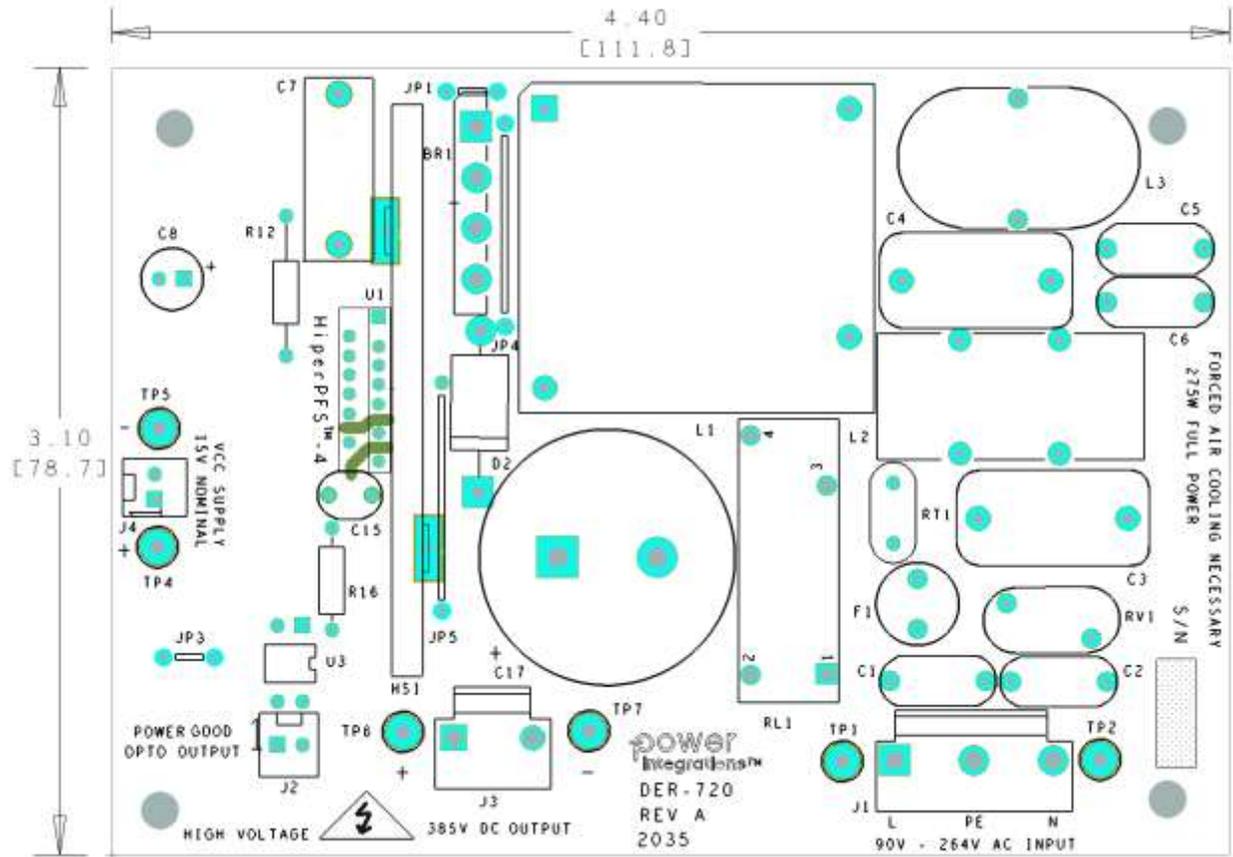


Figure 4 – Printed Circuit Layout, Top.



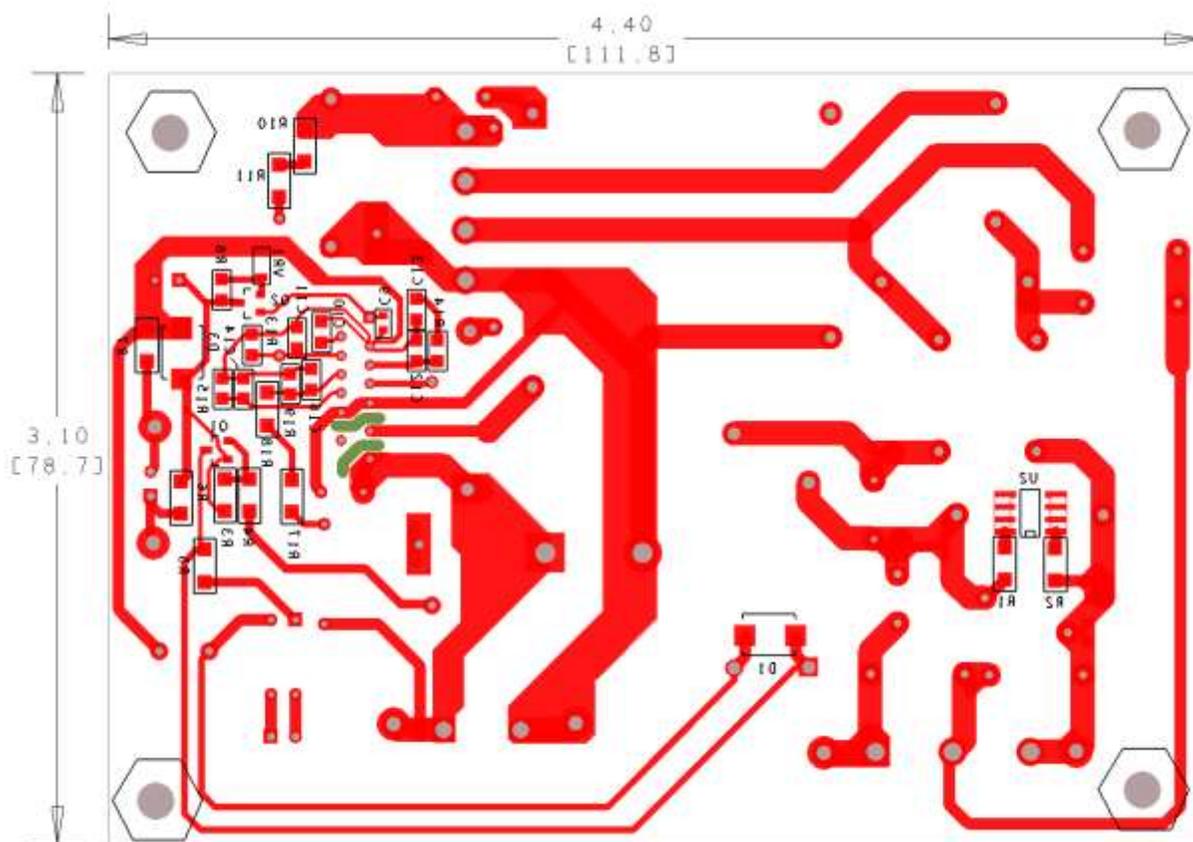


Figure 5 – Printed Circuit Layout, Bottom.

## 6 Bill of Materials

Item	Qty	Ref Des	Description	Mfg Part Number	Mfg
1	1	BR1	800 V, 8 A, Bridge Rectifier, GBU Case	GBU8K-BP	Micro Commercial
2	4	C1 C2 C5 C6	680 pF, Ceramic, Y1	440LT68-R	Vishay
3	2	C3 C4	330 nF, 275 VAC, Film, X2	R46KI333000N1M	Kemet
4	1	C7	680 nF, 450 VDC, Disc Ceramic	ECQ-E2W684KH	Panasonic
5	1	C8	47 $\mu$ F, 50 V, Electrolytic, Gen. Purpose, (6.3 x 11)	EKMGS500ELL470MF11D	Nippon Chemi-Con
6	1	C9	1 $\mu$ F, $\pm$ 10%, 35V, Ceramic, X7R, 0603	C1608X7R1V105K080AE	TDK
7	2	C10 C13	1 $\mu$ F, $\pm$ 10%, 25 V, Ceramic, X7R, 0805	GCM21BR71E105KA56L	Murata
8	2	C11 C16	470 pF, 50 V, Ceramic, X7R, 0805	CC0805KRX7R9BB471	Yageo
9	1	C12	100 nF, 25 V, Ceramic, X7R, 0805	08053C104KAT2A	AVX
10	1	C14	1 nF, 50 V, Ceramic, X7R, 0805	08055C102KAT2A	AVX
11	1	C15	10 nF, 1 kV, Disc Ceramic, X7R	SV01AC103KAR	AVX
12	1	C17	180 $\mu$ F, 450 V, Electrolytic, Snap In, (25 x 30)	ESMQ451VSN181MQ30S	United Chemi-con
13	2	D1 D3	50 V, 1 A, Standard Recovery, GPP, SMB	S1AB-13-F	Diodes, Inc.
14	1	D2	1000 V, 3 A, Rectifier, DO-201AD	1N5408G	ON Semi
15	1	ESIPCLIP_M4_METAL1	Heat Sink Hardware, Edge Clip, 20.76 mm L x 8 mm W x 0.015 mm Thk	NP975864	Aavid Thermalloy
16	1	F1	5 A, 250 V, Slow, TR5	37215000411	Wickman
17	1	HS1	FAB, Heat Sink, PFS, DER394		Custom
18	1	J1	5 Position (1 x 5) header, 0.156 pitch, Vertical	0026604050	Molex
19	2	J2 J4	2 Position (1 x 2) header, 0.1 pitch, Vertical	22-23-2021	Molex
20	1	J3	CONN HEADER 3POS (1x3).156 VERT TIN	0026604030	Molex
21	1	JP1	Wire Jumper, Non-insulated, #22 AWG, 0.2 in	298	Alpha
22	1	JP3	Wire Jumper, Insulated, #24 AWG, 0.2 in	C2003A-12-02	Gen Cable
23	1	JP4	Wire Jumper, Insulated, #24 AWG, 0.8 in	C2003A-12-02	Gen Cable
24	1	JP5	Wire Jumper, Insulated, #24 AWG, 0.9 in	C2003A-12-02	Gen Cable
25	1	L1	Custom, PFC Inductor, 393 $\mu$ H, PQ32/20, Vertical		custom
26	1	L2	9 mH, 5 A, Common Mode Choke	T22148-902S P.I. Custom	Fontaine
27	1	L3	330 $\mu$ H, 3.3 A, Vertical Toroidal	2218-V-RC	Bourns
28	4	POST-CRKT_BRD_6-32_HEX1 POST-CRKT_BRD_6-32_HEX2 POST-CRKT_BRD_6-32_HEX3 POST-CRKT_BRD_6-32_HEX4	Post, Circuit Board, Female, Hex, 6-32, snap, 0.375L, Nylon	561-0375A	Eagle Hardware
29	1	Q1	TRANS PNP 40V 0.6A SOT-23	MMBT4403-7-F	Diodes, Inc.
30	1	Q2	TRANS NPN 40V 0.6A SOT-23	MMBT4401LT1G	On Semi
31	2	R1 R2	RES, 510 k $\Omega$ , 5%, 1/4 W, Thick Film, 1206	ERJ-8GEYJ514V	Panasonic
32	1	R3	RES, 10.0 k $\Omega$ , 1%, 1/4 W, Thick Film, 1206	ERJ-8ENF1002V	Panasonic
33	1	R4	RES, 16.2 k $\Omega$ , 1%, 1/4 W, Thick Film, 1206	ERJ-8ENF1622V	Panasonic
34	1	R5	RES, 3.01 k $\Omega$ , 1%, 1/4 W, Thick Film, 1206	ERJ-8ENF3011V	Panasonic
35	2	R6 R7	RES, 1 $\Omega$ , 1%, 1/4 W, Thick Film, 1206	ERJ-8RQF1R0V	Panasonic
36	1	R8	RES, 2.21 k $\Omega$ , 1%, 1/8 W, Thick Film, 0805	ERJ-6ENF2211V	Panasonic
37	4	R10 R11 R17 R18	RES, 6.2 M $\Omega$ , 1%, 1/4 W, Thick Film, 1206	KTR18EZPF6204	Rohm Semi



38	2	R12 R16	RES, 3.74 M $\Omega$ , 1%, 1/4 W, Metal Film	MFR-25FBF52-3M74	Yageo
39	2	R13 R19	RES, 162 k $\Omega$ , 1%, 1/8 W, Thick Film, 0805	ERJ-6ENF1623V	Panasonic
40	1	R14	RES, 30.1 k $\Omega$ , 1%, 1/8 W, Thick Film, 0805	ERJ-6ENF3012V	Panasonic
41	1	R15	RES, 332 k $\Omega$ , 1%, 1/8 W, Thick Film, 0805	ERJ-6ENF3323V	Panasonic
42	1	RL1	RELAY GEN PURPOSE SPST 8A 12V	G6RL-1A-ASI-DC12	OMRON
43	1	RT1	NTC Thermistor, 2.5 $\Omega$ , 5 A	SL10 2R505	Ametherm
44	1	RTV	Thermally conductive Silicone Grease	120-SA	Wakefield
45	1	RV1	320 VAC, 23 J, 10 mm, RADIAL	V320LA10P	Littlefuse
46	1	SCREW	SCREW MACHINE PHIL 6-32 X 1/4 SS	PMSSS 632 0025 PH	Building Fasteners
47	3	TP1 TP5 TP7	Test Point, BLK, THRU-HOLE MOUNT	5011	Keystone
48	1	TP2	Test Point, WHT, THRU-HOLE MOUNT	5012	Keystone
49	2	TP4 TP6	Test Point, RED, THRU-HOLE MOUNT	5010	Keystone
50	1	U1	HiperPFS-4, ESIP16D	PFS7727H	Power Integrations
51	1	U2	CAPZero-3, SO-8C	CAP003DG	Power Integrations
52	1	U3	Optocoupler, 35 V, CTR 80-160%, 4-DIP	LTV-817A	Liteon
53	1	VR1	13 V, 2%, 300 mW, SOD-323	BZX384-B13,115	NXP Semi
54	1	WASHER	Washer Flat #6, SS, Zinc Plate, 0.267 OD x 0.143 ID x 0.032 Thk	620-6Z	Olander



## 7 Inductor Design Spreadsheet

**Note:** If current density is higher than 6 A / mm<sup>2</sup> on forced air cooling case, a "warning" will be generated. Need for a higher cross section of the wire should be made based on the thermal test result. With sufficient cooling, higher current densities can be used safely.

Hiper_PFS-4_Boost_091020; Rev.1.3; Copyright Power Integrations 2020	INPUT	INFO	OUTPUT	UNITS	Continuous Mode Boost Converter Design Spreadsheet
<b>Enter Application Variables</b>					
Input Voltage Range	Universal		Universal		Input voltage range
VACMIN			90	VAC	Minimum AC input voltage. Spreadsheet simulation is performed at this voltage. To examine operation at other voltages, enter here, but enter fixed value for LPFC_ACTUAL.
VACMAX			265	VAC	Maximum AC input voltage
VBROWNIN			79	VAC	Expected Typical Brown-in Voltage per IC specifications; Line impedance not accounted for.
VBROWNOUT			69	VAC	Expected Typical Brown-out voltage per IC specifications; Line impedance not accounted for.
VO			385	VDC	Nominal load voltage
PO			275	W	Nominal Output power
fL			50	Hz	Line frequency
TA Max			40	°C	Maximum ambient temperature
Efficiency Estimate			0.93		Enter the efficiency estimate for the boost converter at VACMIN. Should approximately match calculated efficiency in Loss Budget section
VO_MIN			366	VDC	Minimum Output voltage
VO_RIPPLE_MAX			20	VDC	Maximum Output voltage ripple
T_HOLDUP	17		17	ms	Holdup time
VHOLDUP_MIN			308	VDC	Minimum Voltage Output can drop to during holdup
I_INRUSH			40	A	Maximum allowable inrush current
Forced Air Cooling	Yes		Yes		Enter "Yes" for Forced air cooling. Otherwise enter "No". Forced air reduces acceptable choke current density and core autopick core size
<b>KP and INDUCTANCE</b>					
KP_TARGET	0.40		0.40		Target ripple to peak inductor current ratio at the peak of VACMIN. Affects inductance value
LPFC_TARGET (0 bias)			393	uH	PFC inductance required to hit KP_TARGET at peak of VACMIN and full load
LPFC_DESIRED (0 bias)			393	uH	LPFC value used for calculations. Leave blank to use LPFC_TARGET. Enter value to hold constant (also enter core selection) while changing VACMIN to examine brownout operation. Calculated inductance with rounded (integral) turns for powder core.
KP_ACTUAL			0.402		Actual KP calculated from LPFC_DESIRED
LPFC_PEAK			393	uH	Inductance at VACMIN and maximum bias current. For Ferrite, same as LPFC_DESIRED (0 bias)
<b>Basic current parameters</b>					
IAC_RMS			3.29	A	AC input RMS current at VACMIN and Full Power load
IO_DC			0.71	A	Output average current/Average diode current
<b>PFS Parameters</b>					
PFS Package	H/L		H/L		HiperPFS package selection
PFS Part Number	PFS7727 H		PFS7727H		If examining brownout operation, over-ride autopick with desired device size
Operating Mode	Full Power		Full Power		Mode of operation of PFS. For Full Power mode enter "Full Power" otherwise enter "EFFICIENCY" to indicate efficiency mode
IOCP min			8.00	A	Minimum Current limit



IOCP typ			8.40	A	Typical current limit
IOCP max			8.80	A	Maximum current limit
IP			5.78	A	MOSFET peak current
IRMS			2.82	A	PFS MOSFET RMS current
RDSOn			0.45	Ohms	Typical RDSon at 100 'C
FS_PK			93.0	kHz	Estimated frequency of operation at crest of input voltage (at VACMIN)
FS_AVG			75.3	kHz	Estimated average frequency of operation over line cycle (at VACMIN)
PCOND_LOSS_PFS			3.611	W	Estimated PFS Switch conduction losses
PSW_LOSS_PFS			2.259	W	Estimated PFS Switch switching losses
PFS_TOTAL			5.870	W	Total Estimated PFS Switch losses
TJ Max			100	deg C	Maximum steady-state junction temperature
Rth-JS			2.80	°C/W	Maximum thermal resistance (Junction to heatsink)
HEATSINK Theta-CA			5.00	°C/W	Maximum thermal resistance of heatsink
<b>INDUCTOR DESIGN</b>					
<b>Basic Inductor Parameters</b>					
LPFC (0 Bias)			393	uH	Value of PFC inductor at zero current. This is the value measured with LCR meter. For powder, it will be different than LPFC.
LP_TOL	7.0		7.0	%	Tolerance of PFC Inductor Value (ferrite only)
IL_RMS			3.32	A	Inductor RMS current (calculated at VACMIN and Full Power Load)
<b>Material and Dimensions</b>					
Core Type	Ferrite		Ferrite		Enter "Sendust", "Iron Powder" or "Ferrite"
Core Material	Auto		PC44/PC95		Select from 60u, 75u, 90u or 125 u for Sendust cores. Fixed at PC44/PC95 for Ferrite cores. Fixed at -52 material for Pow Iron cores.
Core Geometry	Auto		PQ		Toroid only for Sendust and Powdered Iron; EE or PQ for Ferrite cores.
Core	PQ32/20		PQ32/20		Core part number
Ae			170.00	mm^2	Core cross sectional area
Le			55.50	mm	Core mean path length
AL			6530.00	nH/t^2	Core AL value
Ve			9.44	cm^3	Core volume
HT (EE/PQ/EQ/RM/POT) / ID (toroid)			5.12	mm	Core height/Height of window; ID if toroid
MLT			67.1	mm	Mean length per turn
BW			8.98	mm	Bobbin width
LG			1.48	mm	Gap length (Ferrite cores only)
<b>Flux and MMF calculations</b>					
BP_TARGET (ferrite only)	3900		3900	Gauss	Target flux density at worst case: IOCP and maximum tolerance inductance (ferrite only) - drives turns and gap
B_OCP (or BP)			3889	Gauss	Target flux density at worst case: IOCP and maximum tolerance inductance (ferrite only) - drives turns and gap
B_MAX			2385	Gauss	Peak flux density at AC peak, VACMIN and Full Power Load, nominal inductance, minimum IOCP
μ_TARGET (powder only)			N/A	%	target μ at peak current divided by μ at zero current, at VACMIN, full load (powder only) - drives auto core selection
μ_MAX (powder only)			N/A	%	actual μ at peak current divided by μ at zero current, at VACMIN, full load (powder only)
μ_OCP (powder only)			N/A	%	μ at IOCPtyp divided by μ at zero current
I_TEST			8.4	A	Current at which B_TEST and H_TEST are calculated, for checking flux at a current other than IOCP or IP; if blank IOCP_typ is used.
B_TEST			3712	Gauss	Flux density at I_TEST and maximum tolerance inductance
μ_TEST (powder only)			N/A	%	μ at IOCP divided by μ at zero current, at IOCPtyp
<b>Wire</b>					



URNS			56		Inductor turns. To adjust turns, change BP_TARGET (ferrite) or $\mu\_TARGET$ (powder)
ILRMS			3.32	A	Inductor RMS current
Wire type	Litz		Litz		Select between "Litz" or "Magnet" for double coated magnet wire
AWG	38	Info	38	AWG	Selected wire has increased losses due to skin and proximity effects. Consider using multiple strands of thinner wires, Litz wire, or decreasing the number of layers
Filar	40		40		Inductor wire number of parallel strands. Leave blank to auto-calc for Litz
OD (per strand)			0.102	mm	Outer diameter of single strand of wire
OD bundle (Litz only)			0.90	mm	Will be different than OD if Litz
DCR			0.258	ohm	Choke DC Resistance
P AC Resistance Ratio			1.78		Ratio of total copper loss, including HF AC, to the DC component of the loss
J		Warning	10.23	A/mm <sup>2</sup>	Current density is high, if copper loss is high use thicker wire, more strands, or larger core
FIT			99	%	Percentage fill of winding window for EE/PQ core. Full window approx. 90%
Layers			5.91		Estimated layers in winding
<b>Loss calculations</b>					
BAC-p-p			959	Gauss	Core AC peak-peak flux excursion at VACMIN, peak of sine wave
LPFC_CORE_LOSS			0.134	W	Estimated Inductor core Loss
LPFC_COPPER_LOSS			5.056	W	Estimated Inductor copper losses
LPFC_TOTAL_LOSS			5.190	W	Total estimated Inductor Losses
<b>PFC Diode</b>					
PFC Diode Part Number	Auto		Internal		PFS Diode Part Number
Type / Part Number			Qspeed		PFC Diode Type / Part Number
Manufacturer			PI		Diode Manufacturer
VRRM			600.0	V	Diode rated reverse voltage
IF			3.00	A	Diode rated forward current
Qrr			43.0	nC	Qrr at High Temperature
VF			2.10	V	Diode rated forward voltage drop
PCOND_DIODE			1.584	W	Estimated Diode conduction losses
PSW_DIODE			0.236	W	Estimated Diode switching losses
P_DIODE			1.820	W	Total estimated Diode losses
TJ Max			100.0	deg C	Maximum steady-state operating temperature
Rth-JS			N/A	degC/W	Maximum thermal resistance (Junction to heatsink)
HEATSINK Theta-CA			N/A	degC/W	Maximum thermal resistance of heatsink
IFSM			23.0	A	Non-repetitive peak surge current rating. Consider larger size diode if inrush or thermal limited.
<b>Output Capacitor</b>					
COUT	180		180	uF	Minimum value of Output capacitance
VO_RIPPLE_EXPECTED			13.6	V	Expected ripple voltage on Output with selected Output capacitor
T_HOLDUP_EXPECTED			17.5	ms	Expected holdup time with selected Output capacitor
ESR_LF			0.92	ohms	Low Frequency Capacitor ESR
ESR_HF			0.37	ohms	High Frequency Capacitor ESR
IC_RMS_LF			0.54	A	Low Frequency Capacitor RMS current
IC_RMS_HF			1.48	A	High Frequency Capacitor RMS current
CO_LF_LOSS			0.268	W	Estimated Low Frequency ESR loss in Output capacitor
CO_HF_LOSS			0.806	W	Estimated High frequency ESR loss in Output capacitor
Total CO LOSS			1.074	W	Total estimated losses in Output Capacitor
<b>Input Bridge (BR1) and Fuse (F1)</b>					
I <sup>2</sup> t Rating			12.64	A <sup>2</sup> *s	Minimum I <sup>2</sup> t rating for fuse
Fuse Current rating			5.13	A	Minimum Current rating of fuse
VF			0.90	V	Input bridge Diode forward Diode drop
IAVG			3.19	A	Input average current at VBROWNOUT.



PIV_INPUT BRIDGE			375	V	Peak inverse voltage of input bridge
PCOND_LOSS_BRIDGE			5.325	W	Estimated Bridge Diode conduction loss
CIN	0.68		0.68	uF	Input capacitor. Use metallized polypropylene or film foil type with high ripple current rating
CIN_DF			0.001		Input Capacitor Dissipation Factor (tan Delta)
CIN_PLOSS			0.005	W	Input Capacitor Loss
RT1			9.37	ohms	Input Thermistor value
D_Precharge			1N5407		Recommended precharge Diode
<b>PFS4 small signal components</b>					
C_REF			1.0	uF	REF pin capacitor value
RV1			4.0	MOhms	Line sense resistor 1
RV2			6.0	MOhms	Line sense resistor 2
RV3			6.0	MOhms	Typical value of the lower resistor connected to the V-PIN. Use 1% resistor only!
RV4			161.6	kOhms	Description pending, could be modified based on feedback chain R1-R4
C_V			0.495	nF	V pin decoupling capacitor (RV4 and C_V should have a time constant of 80us) Pick the closest available capacitance.
C_VCC			1.0	uF	Supply decoupling capacitor
C_C			100	nF	Feedback C pin decoupling capacitor
Power good Vo lower threshold VPG(L)			333	V	Vo lower threshold voltage at which power good signal will trigger
PGT set resistor			333.0	kohm	Power good threshold setting resistor
<b>Feedback Components</b>					
RFB_1			4.00	Mohms	Feedback network, first high voltage divider resistor
RFB_2			6.00	Mohms	Feedback network, second high voltage divider resistor
RFB_3			6.00	Mohms	Feedback network, third high voltage divider resistor
RFB_4			161.6	kohms	Feedback network, lower divider resistor
CFB_1			0.495	nF	Feedback network, loop speedup capacitor. (R4 and C1 should have a time constant of 80us) Pick the closest available capacitance.
RFB_5			25.5	kohms	Feedback network: zero setting resistor
CFB_2			1000	nF	Feedback component- noise suppression capacitor
<b>Loss Budget (Estimated at VACMIN)</b>					
PFS Losses			5.870	W	Total estimated losses in PFS
Boost diode Losses			1.820	W	Total estimated losses in Output Diode
Input Bridge losses			5.325	W	Total estimated losses in input bridge module
Input Capacitor Losses			0.005	W	Total estimated losses in input capacitor
Inductor losses			5.190	W	Total estimated losses in PFC choke
Output Capacitor Loss			1.074	W	Total estimated losses in Output capacitor
EMI choke copper loss			1.079	W	Total estimated losses in EMI choke copper
Total losses			20.363	W	Overall loss estimate
Efficiency			0.93		Estimated efficiency at VACMIN, full load.
<b>CAPZero component selection recommendation</b>					
CAPZero Device			CAP200DG		(Optional) Recommended CAPZero device to discharge X-Capacitor with time constant of 1 second
Total Series Resistance (Rcapzero1+Rcapzero2)			0.602	MOhms	Maximum Total Series resistor value to discharge X-Capacitors
<b>EMI filter components recommendation</b>					
CX2			680	nF	X capacitor after differential mode choke and before bridge, ratio with Po
LDM_calc			186	uH	Estimated minimum differential inductance to avoid <10kHz resonance in input current
CX1			470	nF	X capacitor before common mode choke, ratio with Po
LCM			10.0	mH	typical common mode choke value
LCM_leakage			30	uH	estimated leakage inductance of CM choke, typical from 30~60uH
CY1 (and CY2)			220	pF	typical Y capacitance for common mode noise suppression



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LDM_Actual			156	uH	cal_LDM minus LCM_leakage, utilizing CM leakage inductance as DM choke.
DCR_LCM			0.070	Ohms	Total DCR of CM choke for estimating copper loss
DCR_LDM			0.030	Ohms	Total DCR of DM choke(or CM #2) for estimating copper loss

**Notes:**

- 1) This design is intended for forced air cooling only. By using fewer strands in the Litz wire (ie. overall smaller O.D.) and running at a higher current density a smaller core size can be used.
- 2) CX2 can be placed between CM chock and DM choke depending on EMI design requirement.



## 8 Switching Inductor Specification

### 8.1 Electrical Diagram

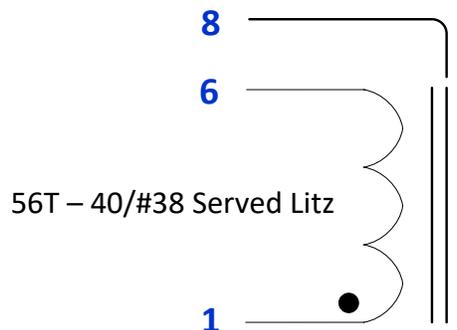


Figure 6 – Inductor Electrical Diagram.

### 8.2 Electrical Specifications

<b>Inductance</b>	Pins 1-6, measured at 100 kHz, 0.4 V <sub>RMS</sub> .	393 $\mu$ H $\pm$ 7%
<b>Resonant Frequency</b>	Pins 1-6.	1300 kHz (Min.)

### 8.3 Materials

Item	Description
[1]	Core: TDK Core: PC44PQ32/20Z-12, and gapped ALG 125 nH/T <sup>2</sup> .
[2]	Bobbin: BPQ32/20-112CPFR - TDK.
[3]	Magnet Wire: 40 x #38_Served Litz.
[4]	Bus Wire: #24 AWG, Connects to Pin 8.
[5]	Tape: 3M 1298 Polyester Film, 17.5 mm Wide, 2.0 mils Thick, or Equivalent.
[6]	Varnish: Dolph BC-359, or Equivalent.

### 8.4 Inductor Build Diagram

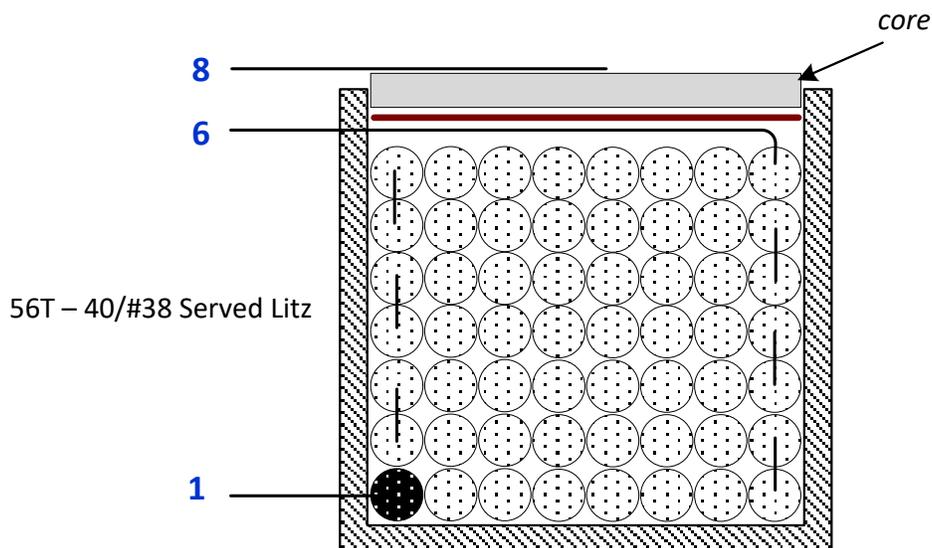
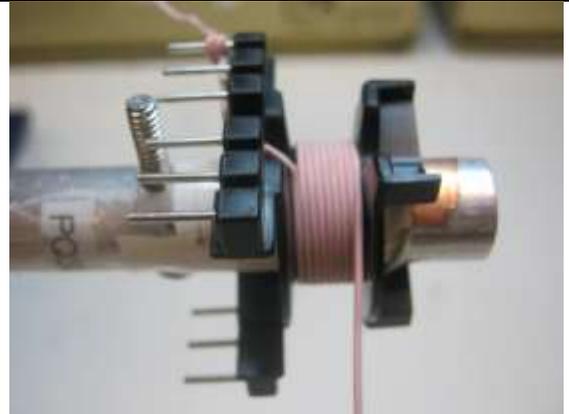


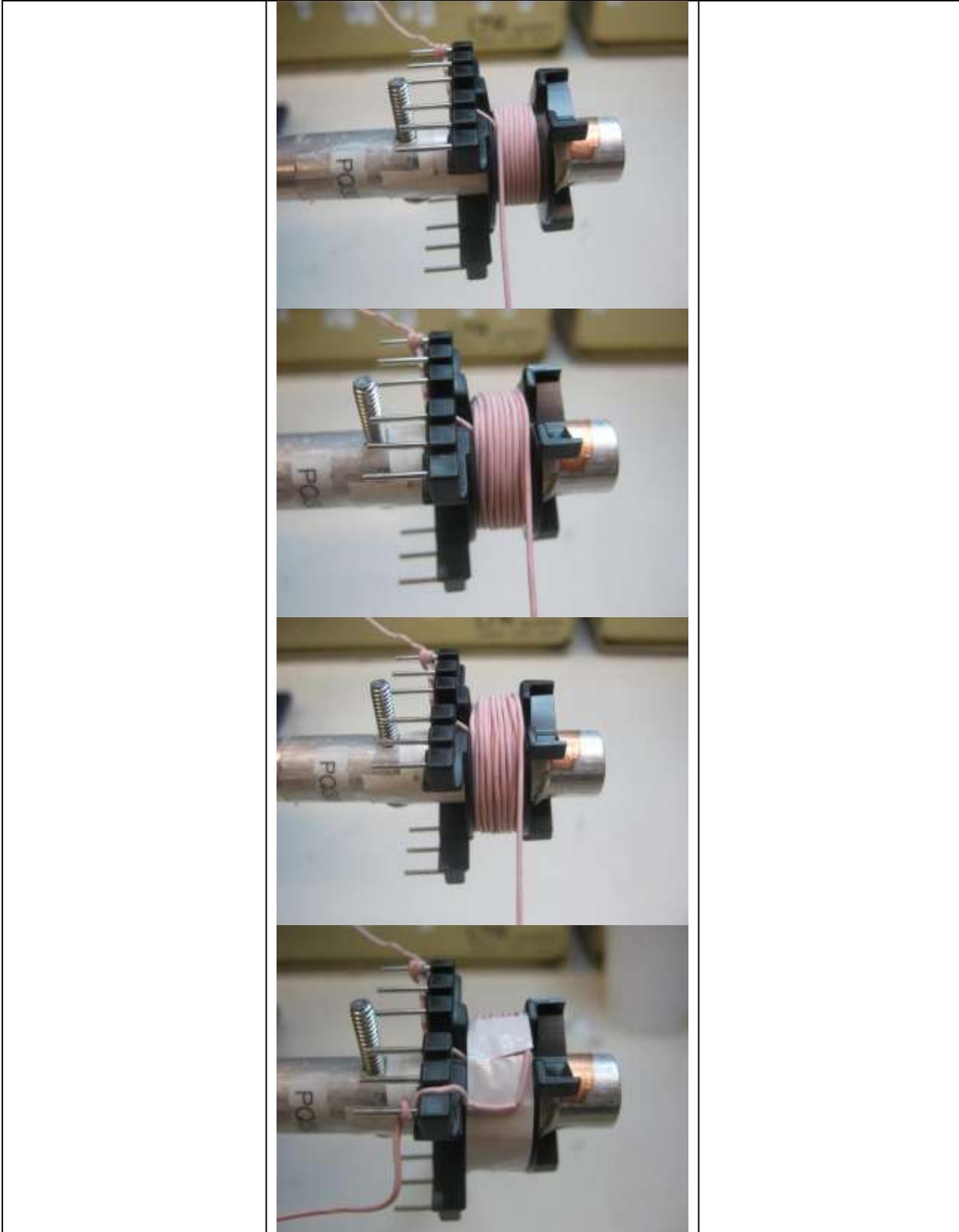
Figure 7 – Inductor Build Diagram.

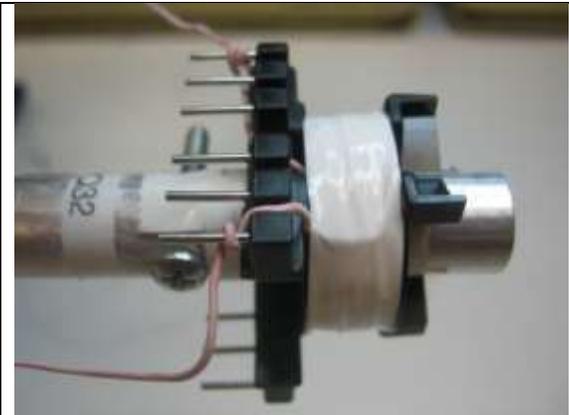
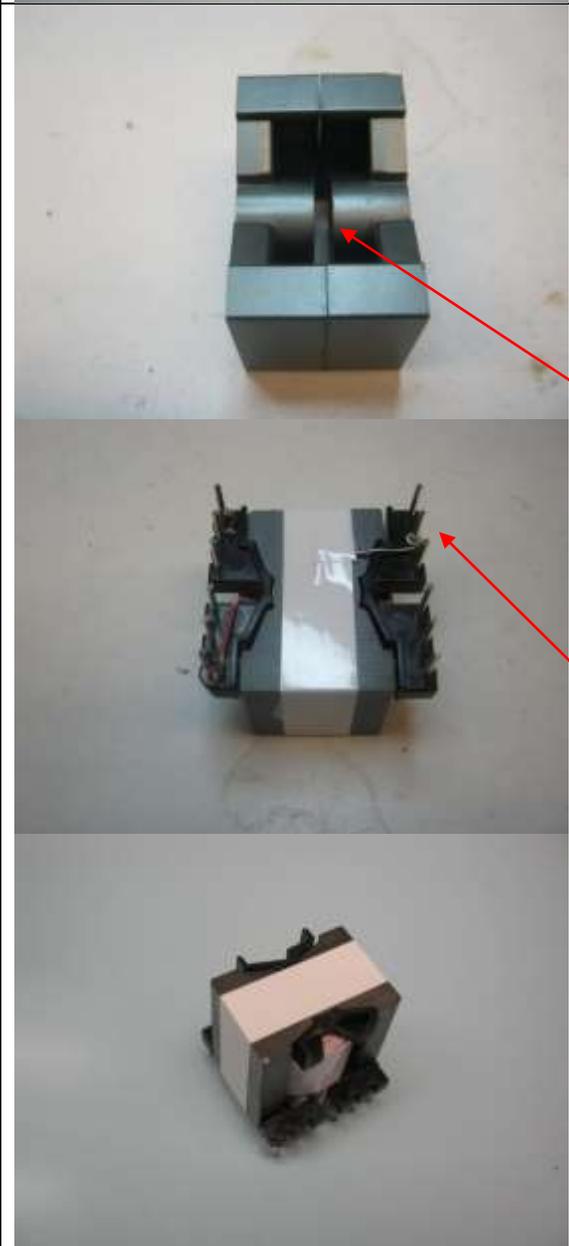
### 8.5 Inductor Construction

<b>Winding Preparation</b>	Place the bobbin on the mandrel with the pin side is on the left side. Winding direction is clockwise direction.
<b>Winding</b>	Start at pin 1, wind 56 turns of wire Item [3] in 7 layers (8T/layer). At the last turn, terminate at pin 6. Apply tape Item [5] to secure the winding.
<b>Final Assembly</b>	Grind both core center legs equally to get 393 $\mu$ H. Remove pins 2, 3, 4, 5, 7, 9, 10 and 11. Attach a bare-wire Item [4] to the bottom core's surface and wrap tape to secure the wire and core halves. Terminate the bare-wire at pin 8. Varnish with Item [6].

8.6 **Winding Illustrations**

<p><b>Winding Preparation</b></p>		<p>Place the bobbin on the mandrel with the pin side is on the left side. Winding direction is clockwise direction.</p>
<p><b>Winding</b></p>		<p>Start at pin 1,</p>
		<p>Wind 56 turns of wire Item [3] in 7 layers (8T/layer). At the last turn, terminate at pin 6.</p>

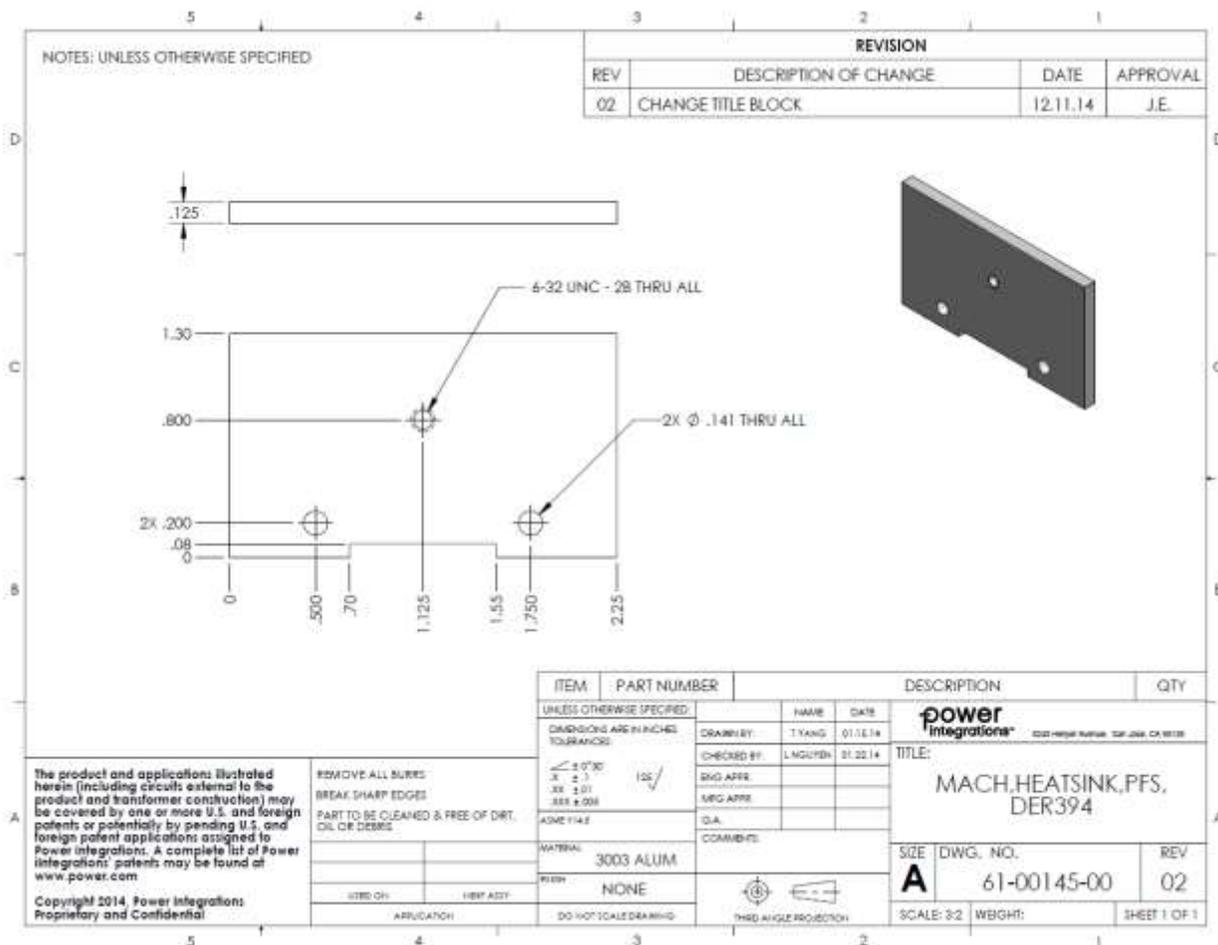


		<p>Apply tape Item [5] to secure the winding.)</p>
<p><b>Final Assembly</b></p>		<p>Grind both core center legs equally to get 393 <math>\mu</math>H.</p> <p>Attach a bare-wire Item [4] to the bottom core's surface and wrap tape to secure the wire and core halves. Terminate the bare-wire at pin 8. Remove pins 2, 3, 4, 5, 7, 9, 10 and 11.</p> <p>Varnish with Item [6].</p>

## 9 eSIP U1 Heat Sink

(Note: The heat sink was designed for operation with forced air cooling for all operation conditions.)

### 9.1 eSIP U1 Heat Sink Machining Drawing



9.2 **eSIP U1 Heat Sink Fabrication Drawing**

NOTES: UNLESS OTHERWISE SPECIFIED  
 ▲ SUPPLIER TO INSTALL EYELET, ITEM 2, TO HEATSINK, ITEM 1.

REVISION			
REV	DESCRIPTION OF CHANGE	DATE	APPROVAL
02	CHANGE TITLE BLOCK	12.11.14	J.E.

ITEM	PART NUMBER	DESCRIPTION	QTY
2	60-00016-00	TERMINAL EYELET, ZIERICK PN 190	2
1	61-00145-00	MACH. HEATSINK, PFS, DER394	1

UNLESS OTHERWISE SPECIFIED:		DATE	
DIMENSIONS ARE IN INCHES TOLERANCES		DATE	
± 0.005 .XX ± 0.1 .XXX ± 0.01	125/	DRAWN BY: T. YANG CHECKED BY: ENG APPR: MFG APPR: D.A. COMMENTS:	TITLE: <b>FAB. HEATSINK, PFS, DER394</b>
MATERIAL: SEE BOM	FINISH: N/A		SIZE DWG. NO. REV <b>A</b> 61-00145-01 02
REMOVE ALL BURRS BREAK SHARP EDGES PART TO BE CLEANED & FREE OF DIRT, OIL OR DEBRIS	DO NOT SCALE DRAWING	SCALE: 1:1	SHEET 1 OF 1

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### 9.3 eSIP U1 Assembly to Heat Sink Drawing

NOTES: UNLESS OTHERWISE SPECIFIED

REVISION			
REV	DESCRIPTION OF CHANGE	DATE	APPROVAL
02	CHANGE TITLE BLOCK	12.11.14	J.E.

ITEM	PART NUMBER	DESCRIPTION	QTY
4	75-0007-00	SCREW MACHINE PHL 6-32 X 1/4 SS	1
5	75-00167-00	WASHER PLAT #6-32 ZINC PLATE 3x700X1430H 002H4	1
4	60-00042-00	HEATSINK HEW EDGE CLIP 20.75mmX38mmX90.015mmTWR	1
3	10-0040-00	HEW eSIP-3 PFS7527H w/PT1613	1
2	44-00054-00	THERMALLY CONDUCTIVE SLICHSIE GRSASE	AVR
1	61-00145-00	FAB HEATSINK PFS DER394	1

DATE	BY	CHKD	FILE
2014-11-11	J.E.	P.3114	

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DER-720 275 W PFC FRONT-END  
 PART 61-00145-00 61-00145-00 61-00145-00  
 DL 24 2014

**power integrations**  
 ASSY HEATSINK PFS DER394  
 TYPE: B DWG. NO: 61-00145-02 REV: 02  
 SCALE: 1:1 SHEET 1 OF 1



### 10 Performance Data

All measurements performed at room temperature, 60 Hz input frequency for voltages below 150 VAC and input frequency of 50 Hz for 150 VAC and higher.

During operation, an 80 mm fan was placed next to the board. Picture of measurement set up can be found in Figures in appendix.

#### 10.1 No-Load/Light Load Input Power

To measure no-load/light load input power, the UUT was operated with the relay and power good disabled by removing Q1 and R4. The contacts of relay RL1 were shorted with a wire jumper to bypass inrush thermistor RT1. Input power was measured using a Yokogawa WT210 set for integration mode, with an integration time of 20 minutes.

The UUT was operated with an auxiliary  $V_{CC}$  of 12 V.  $V_{CC}$  voltage and current were measured as 12.57 V and 0.42 mA, resulting in a  $V_{CC}$  power consumption of 5.3 mW.

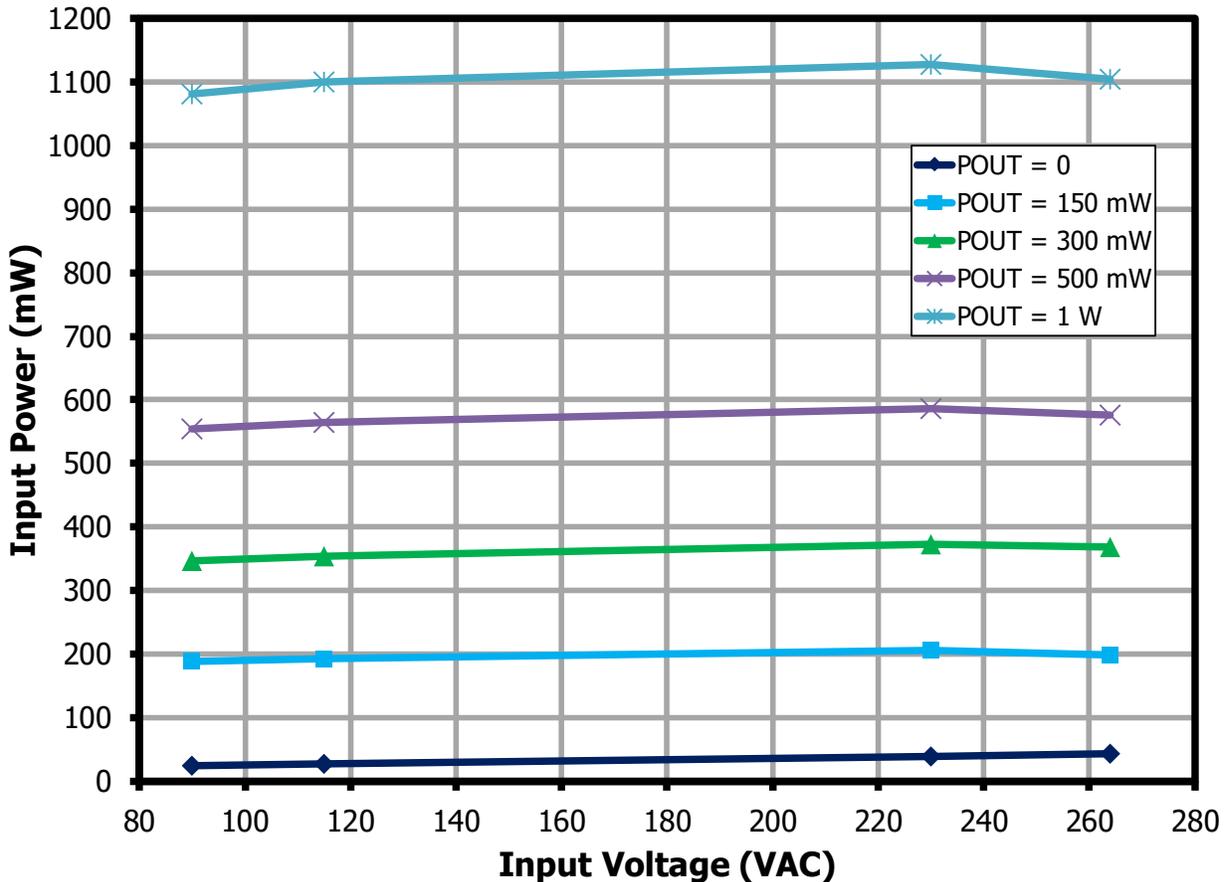


Figure 8 – No-Load/Light Load Input Power (with Vcc Consumption).

90 VAC		115 VAC		230 VAC		264 VAC	
$P_{OUT}$ (mW)	$P_{IN}$ (mW)	$P_{OUT}$ (mW)	$P_{IN}$ (mW)	$P_{OUT}$ (mW)	$P_{IN}$ (mW)	$P_{OUT}$ (mW)	$P_{IN}$ (mW)
0	23.98	0	26.93	0	38.14	0	43.64
150.15	189.02	150.15	192.72	150.15	205.53	150.15	199.09
300.3	346.77	300.3	353.88	300.3	372.35	300.3	368.44
497.25	553.56	497.25	564.93	497.25	585.72	497.25	576.57
998.4	1082.02	998.4	1100.68	998.4	1127.56	998.4	1105.24



### 10.2 PFC Efficiency

Note: To obtain total efficiency, the 12 V consumption including relay was added to the input power.

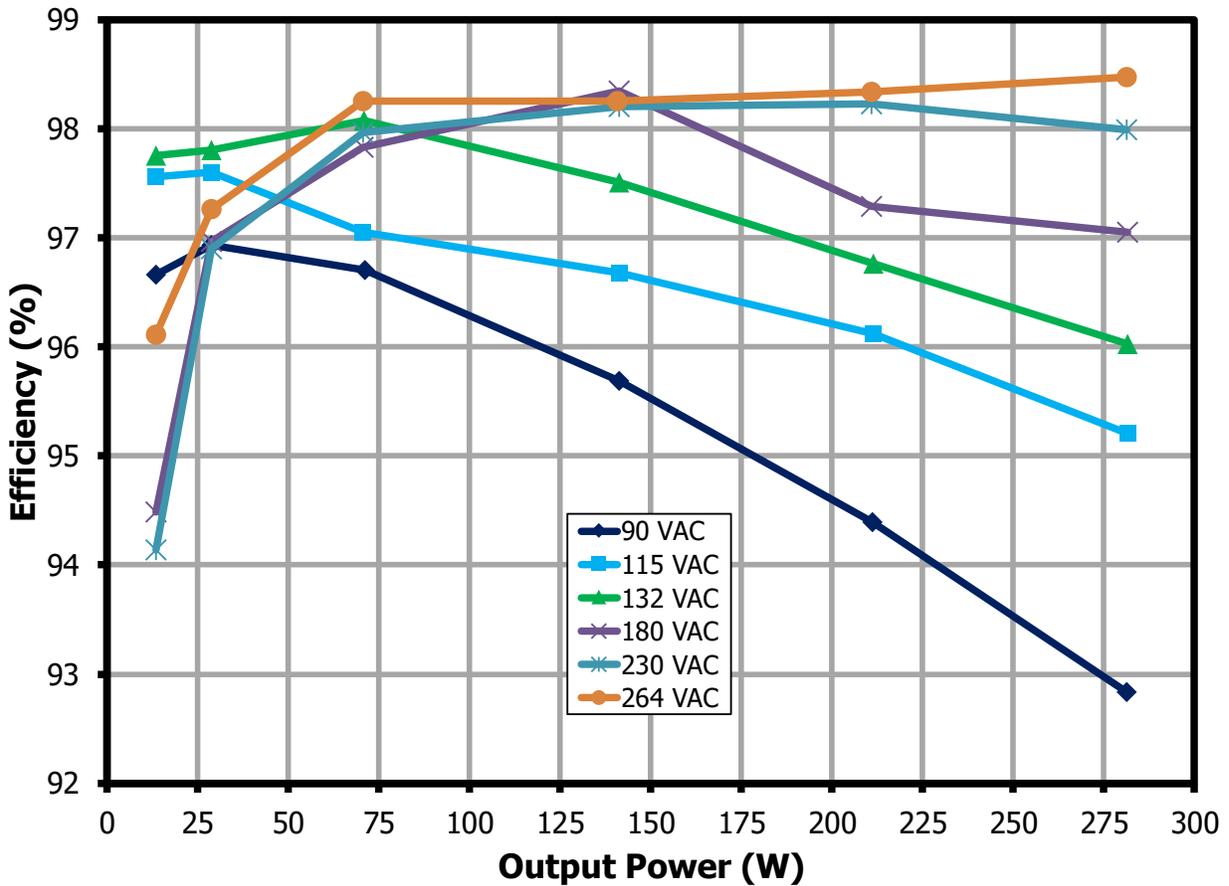


Figure 9 – Efficiency vs. Output Power.

### 10.3 Power Factor

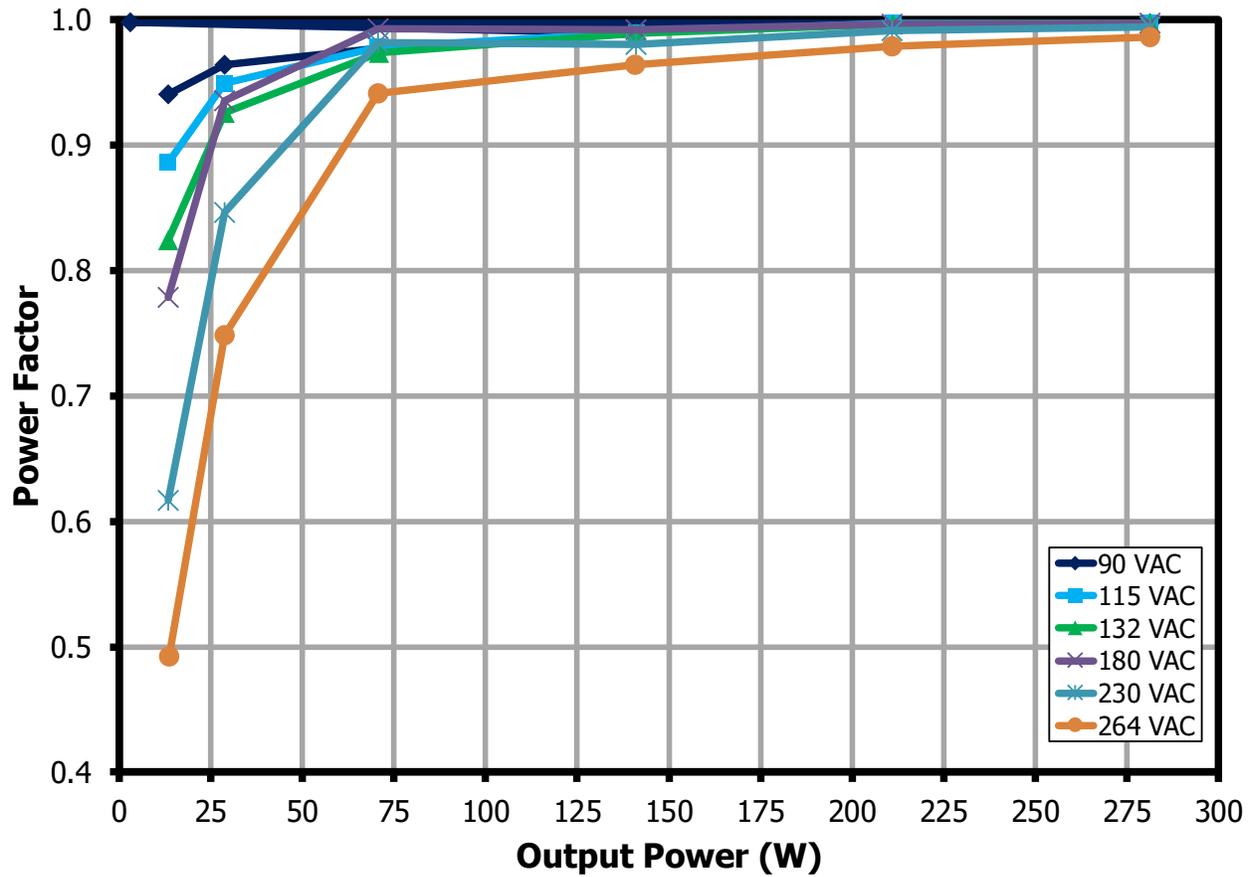


Figure 10 – Input Power Factor vs. Output Power.

### 10.4 Regulation

#### 10.4.1 Load Regulation

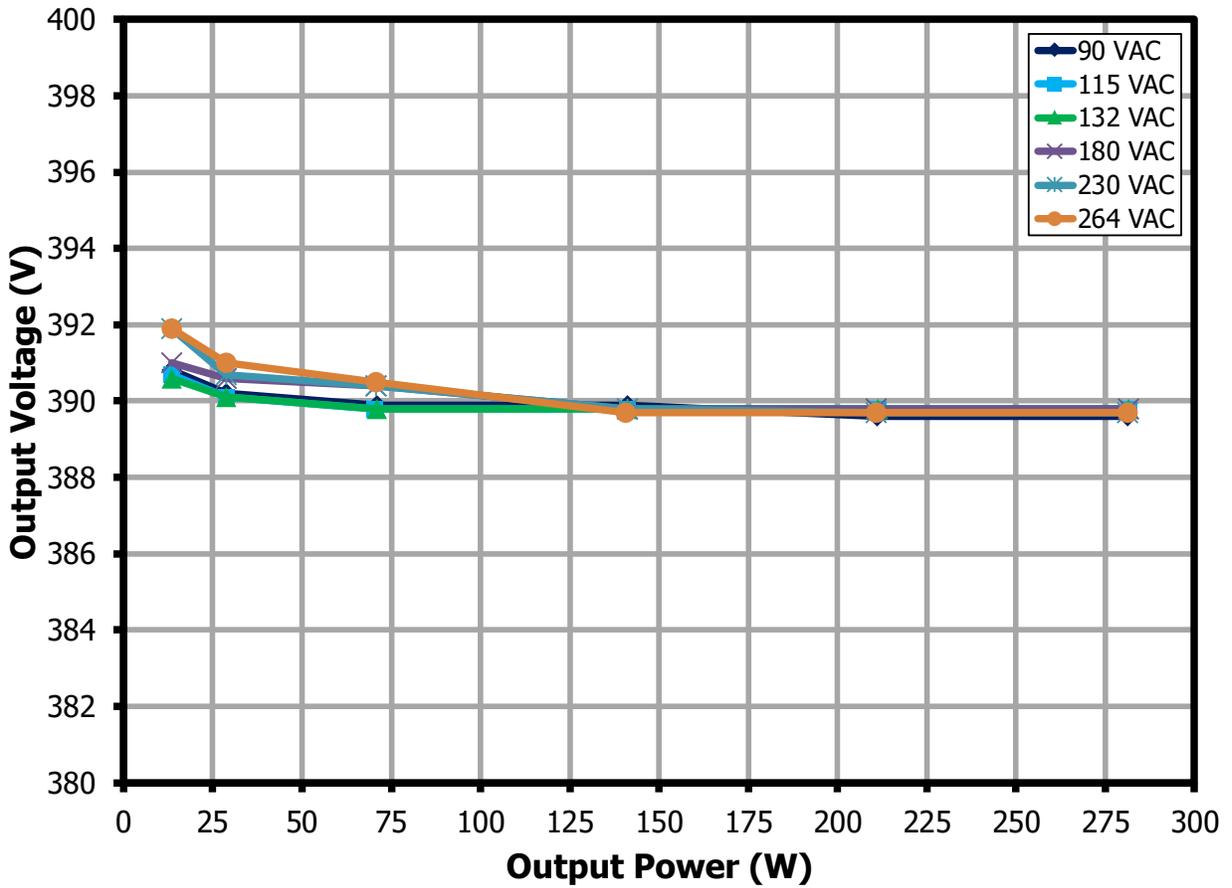


Figure 11 – Load Regulation.

10.4.2 Line Regulation

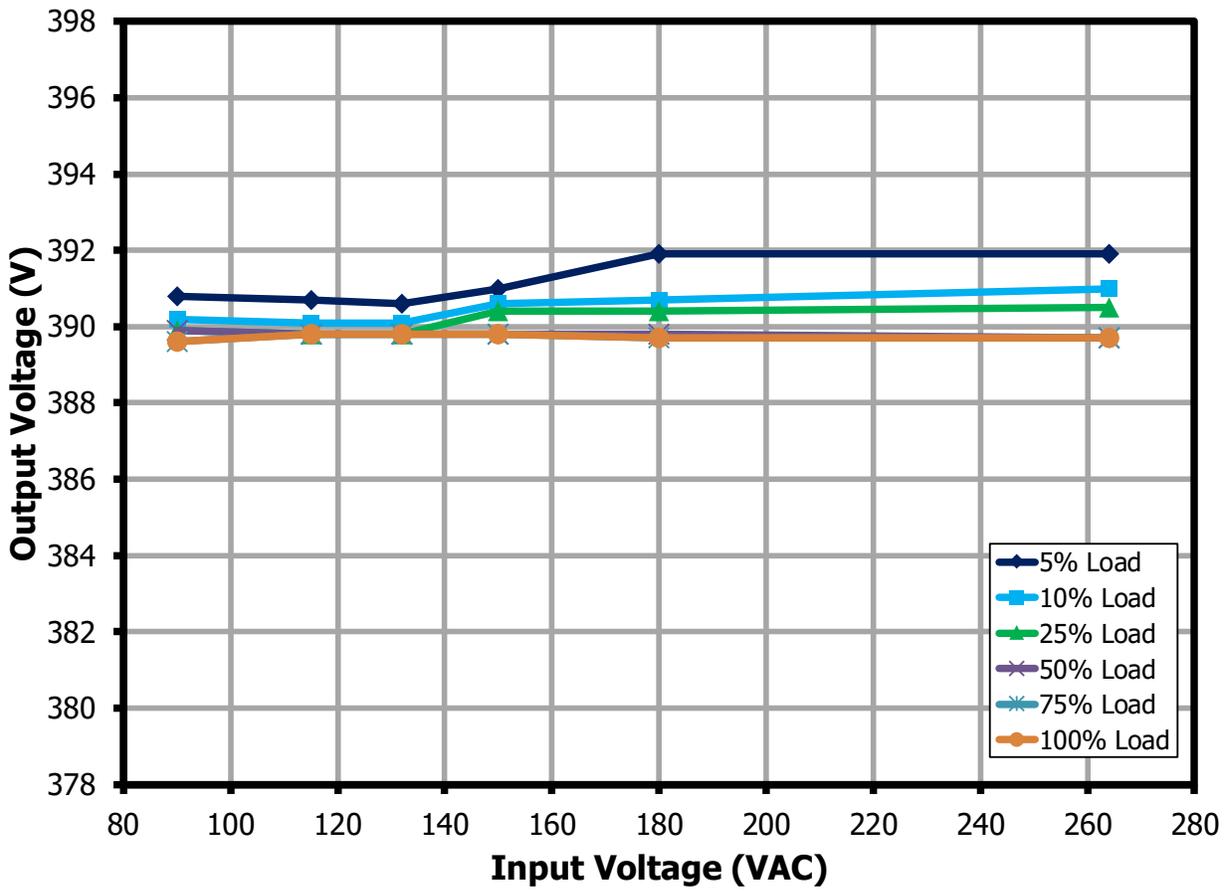
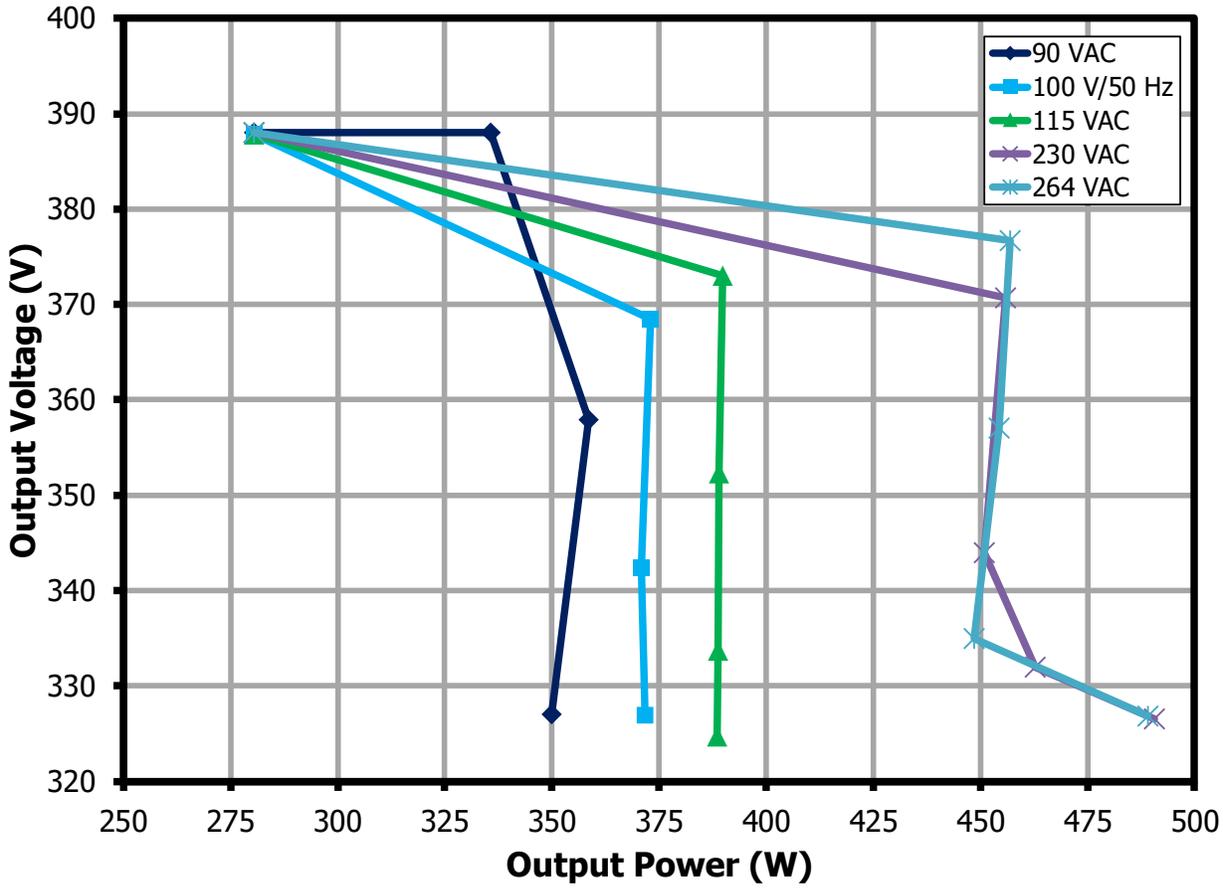


Figure 12 – Line Regulation.

10.5 **Overload**



**Figure 13** – Overload Regulation.

**Note:** 275 W is rated full load for this board design.

10.6 THD

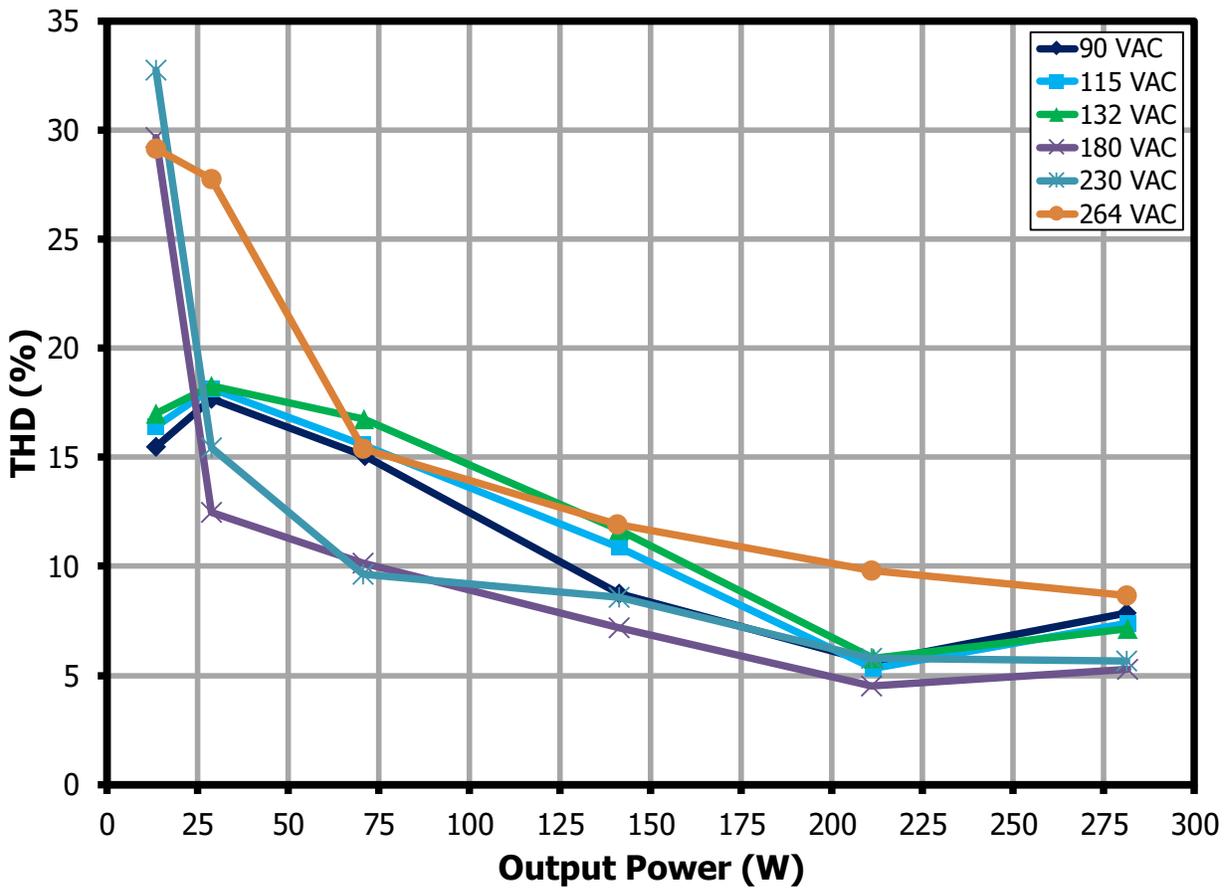


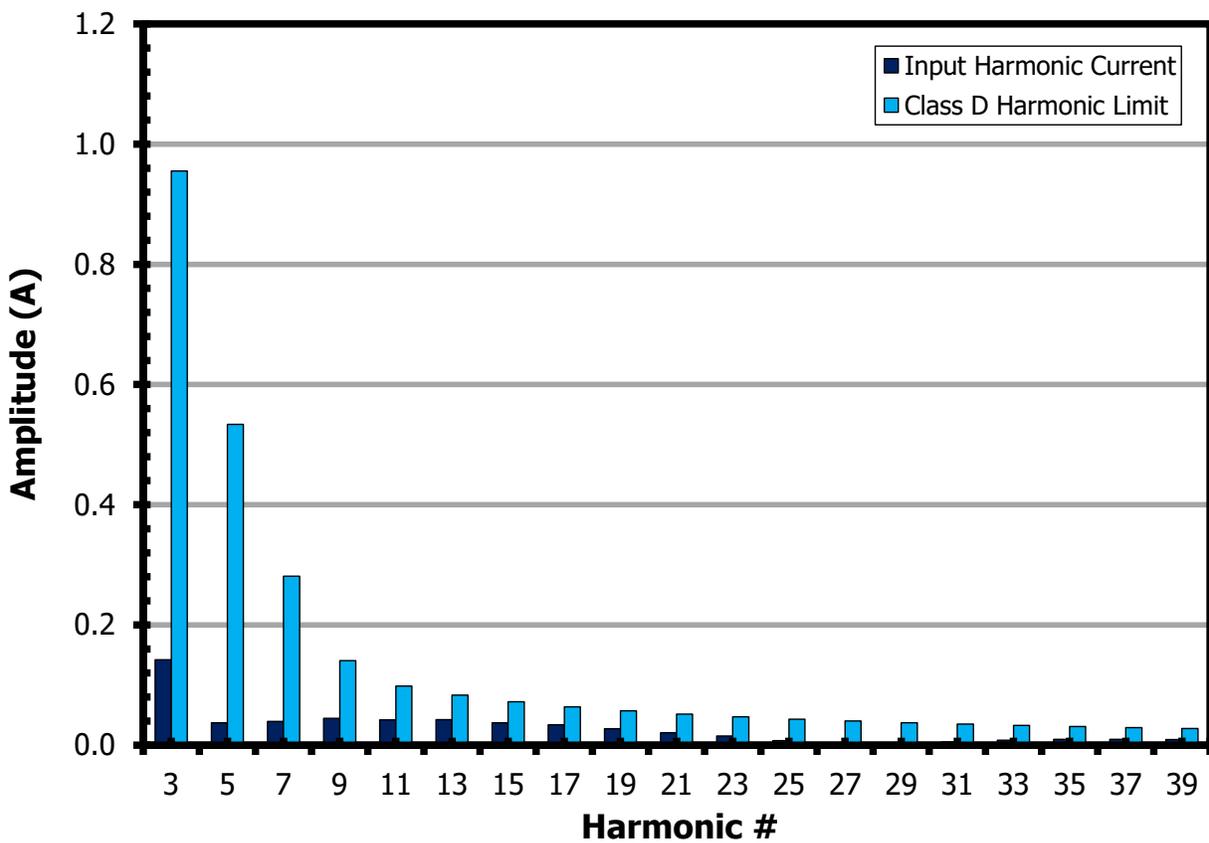
Figure 14 – Input Current THD vs. Load.

**Note:** When on highline (230 VAC and 264 VAC) and 10% load the unit is in bust mode, making the THD reading very high. To get an accurate reading the light load THD value should be integrated over several minutes.

10.7 **Input Current Harmonic Distortion (IEC 61000-3-2 Class-D)**

10.7.1 Measured at 115 VAC Input 60 Hz.

10.7.1.1 50% Load at Output



**Figure 15** – Amplitude of Input Current Harmonics for 50% Load at 115 VAC Input.

10.7.1.2 100% Load at Output

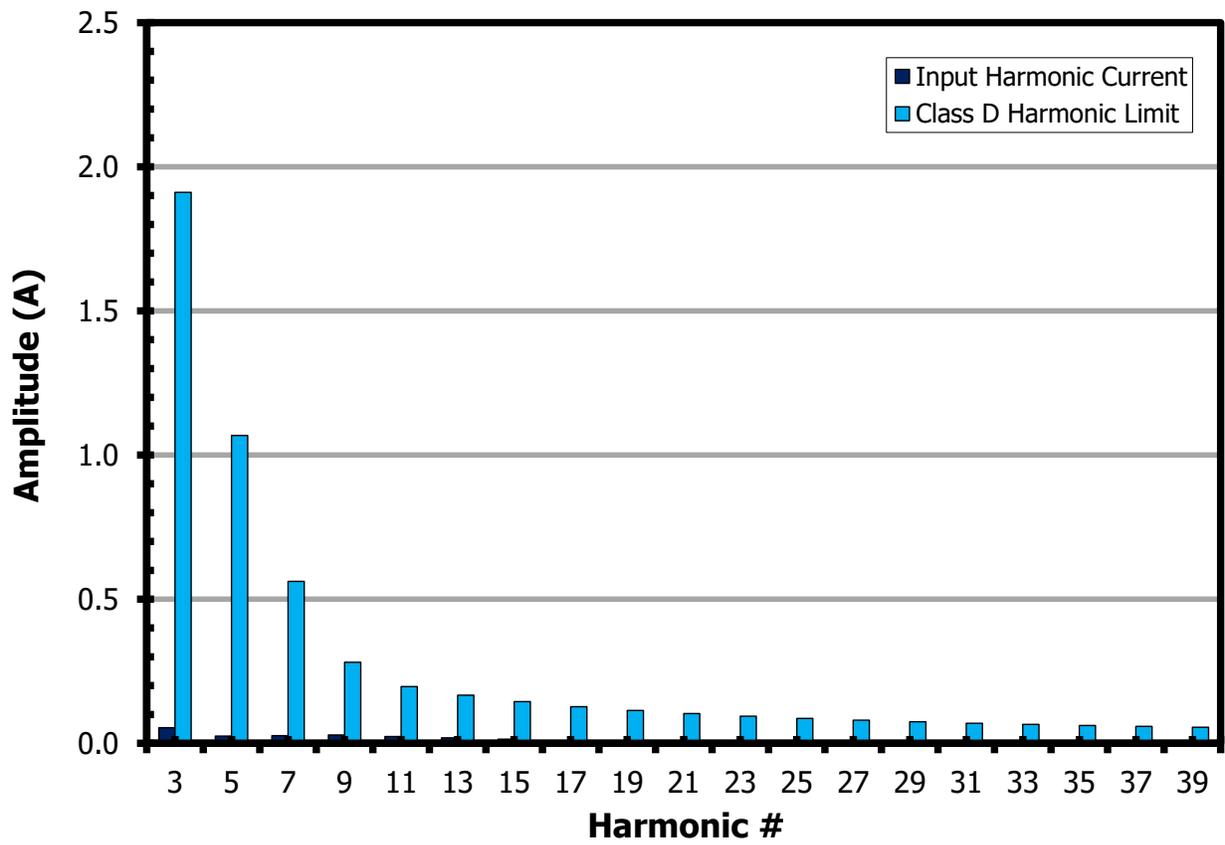


Figure 16 – Amplitude of Input Current Harmonics for 100% Load at 115 VAC Input.

10.7.2 Measured at 230 VAC Input 50 Hz.

10.7.2.1 50% Load at Output

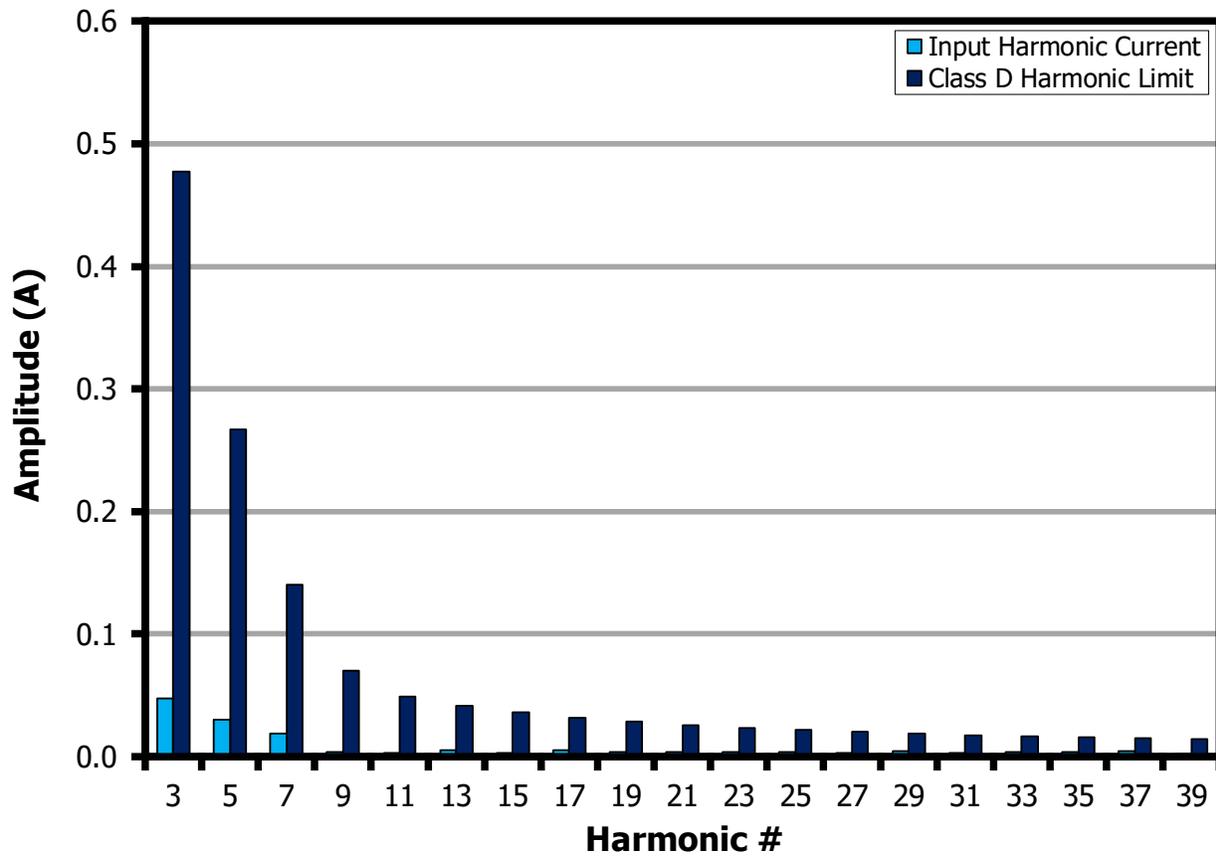


Figure 17 – Amplitude of Input Current Harmonics for 50% Load at 230 VAC Input.

10.7.2.2 100% Load at Output

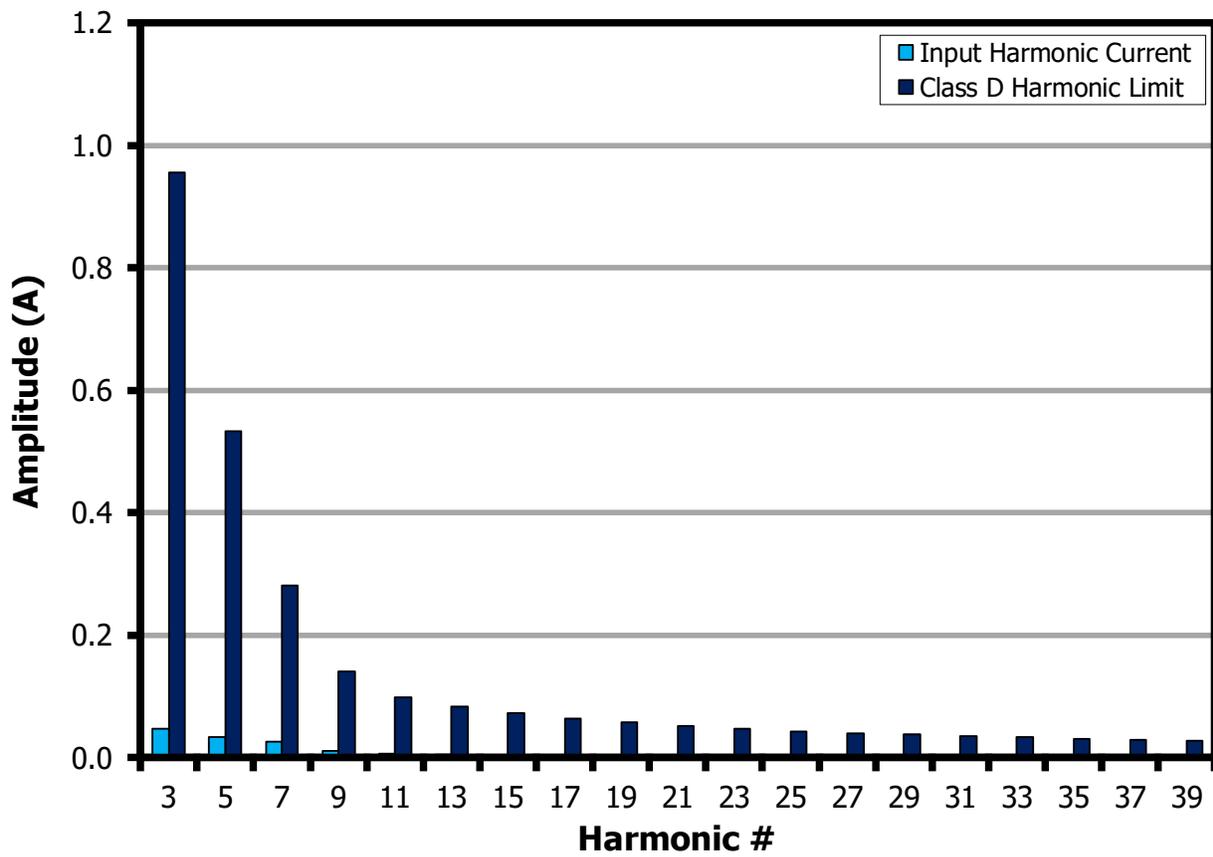


Figure 18 – Amplitude of Input Current Harmonics for 100% Load at 230 VAC Input.

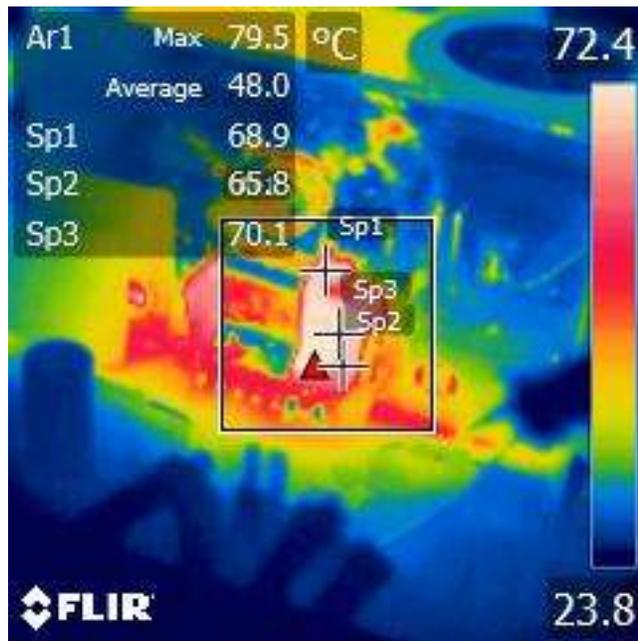
## 11 Thermal Performance

A 80 mm 12 VDC fan powered by 10 VDC supply to create a 200 LFM air flow was placed as shown in Appendix 1 with the UUT running at full load. The unit was allowed to reach thermal equilibrium [ $\sim 2$  hrs.] prior to thermal measurement with a FLIR camera. Table 1 shows full load temperature of key components measured at equilibrium, room temperature and with forced air cooling. See Appendix 1 for set-up.

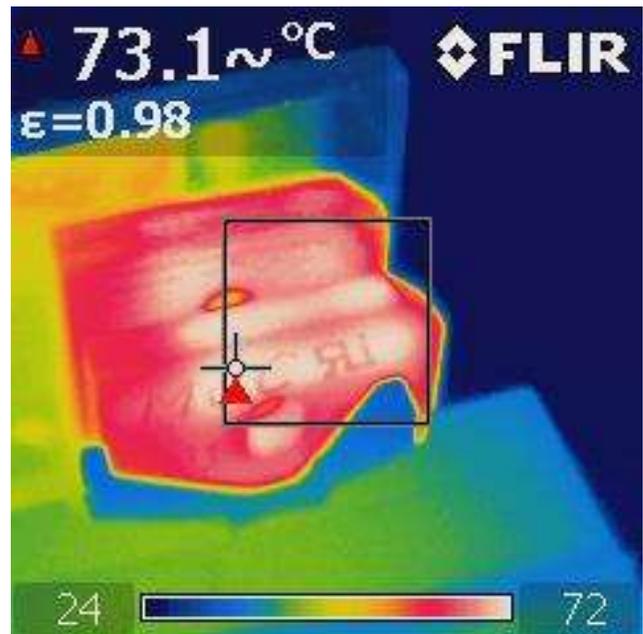
Temperature (°C) 278 W Load			
Component		115 VAC	230 VAC
Ambient (measured by thermocouple)		22	25
CM Inductor	L2	36	26.7
DM Inductor	L3	32.1	25.9
Main Inductor	L1 Wire	54.9	35.4
	L1 Core	42.7	32.1
X1 Capacitor	C3	28.5	26.6
X2 Capacitor	C4	31.1	27.1
Bridge Capacitor	C5	32.2	28
Bridge Rectifier	BR1	73.1	48.3
Output Capacitor	C13	35.6	30.8
Heat Sink Top (Close to PFS7727H)		68.9	41.1
PFS7727H	U1 MOSFET	79.5	48
	U1 Diode	70.1	42.3

**Table 1** – Steady-State Thermal Performance.

11.1 **115 VAC Thermal Measurements**

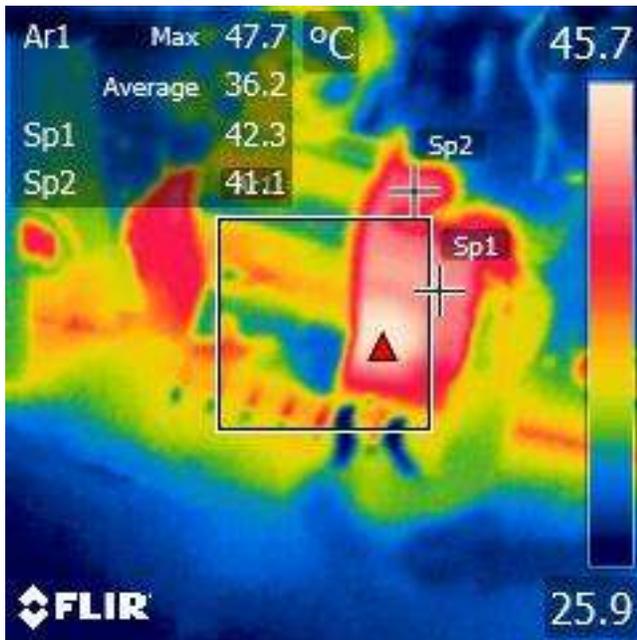


**Figure 19** – Infrared Images of HiperPFS-4 MOSFET and Diode at Thermal Equilibrium, 115 VAC, Full Load, with Forced-Air Flow.  
 AR1: HiperPFS-4 MOSFET Hot Spot = 79.5 °C.  
 SP3: HiperPFS-4 Output Diode = 70.1 °C.  
 SP1: Heat Sink Temperature Near HiperPFS-4 = 68.9 °C.

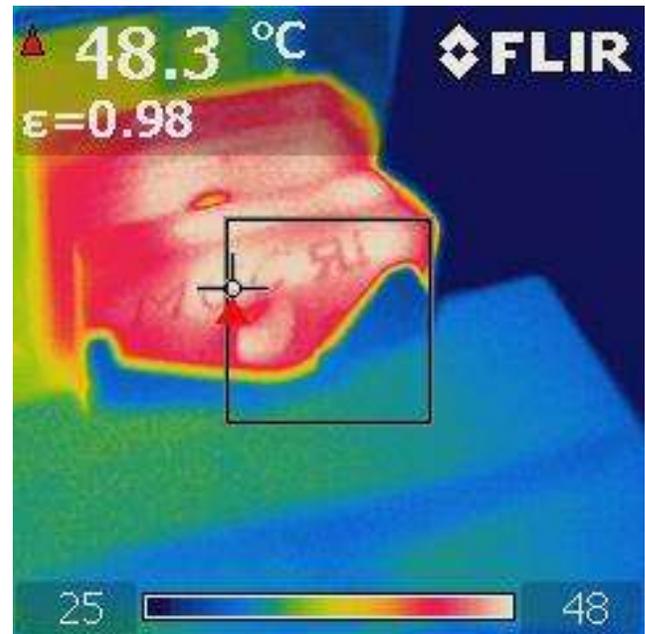


**Figure 20** – Infrared Images of Bridge at Thermal Equilibrium, 115 VAC, Full Load, with Forced-Air Flow.  
 Hot Spot Temperature = 73.1 °C.

11.2 **230 VAC Thermal Measurements**



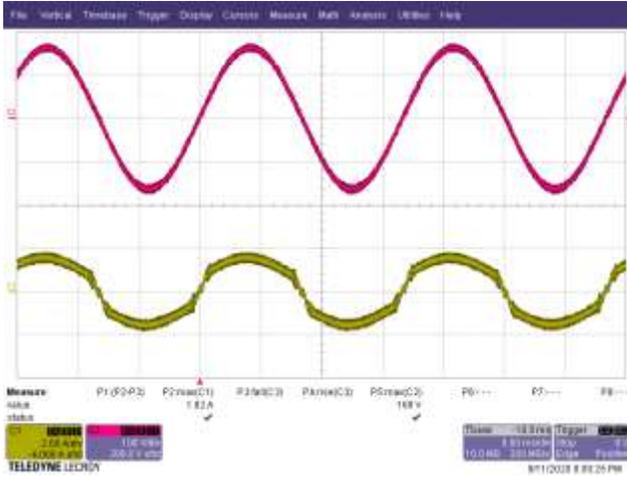
**Figure 21** – Infrared Image of HiperPFS-4 MOSFET and Diode at Thermal Equilibrium, 230 VAC, Full Load, with Forced-Air Flow.  
 AR1: HiperPFS-4 MOSFET Hot Spot = 47.7 °C.  
 SP1: HiperPFS-4 Output Diode = 42.3 °C.  
 SP2: Heat Sink Temperature Near HiperPFS-4 = 41.1 °C.



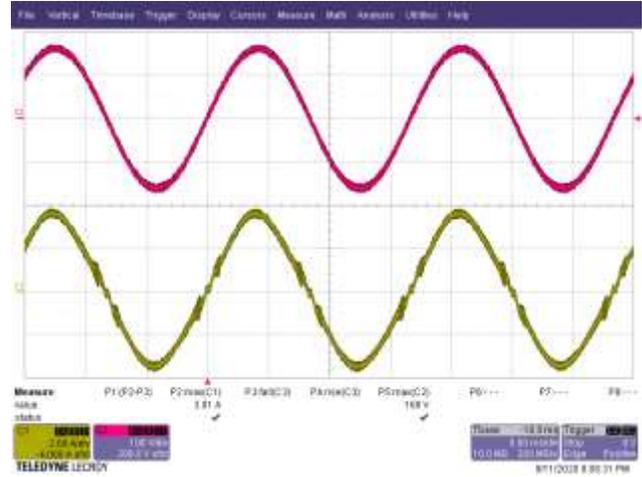
**Figure 22** – Infrared Image of Bridge at Thermal Equilibrium, 230 VAC, Full Load, with Forced-Air Flow.  
 Hot Spot Temperature = 48.3 °C.

## 12 Input Waveforms

### 12.1 Input Current at 115 VAC and 60 Hz

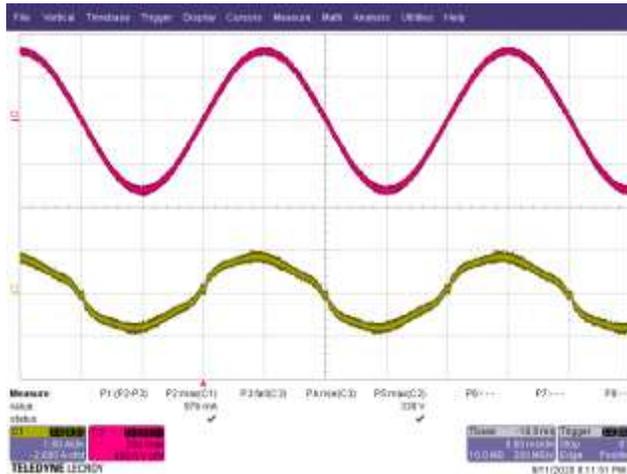


**Figure 23** – 115 VAC, 50% Load.  
 Upper:  $V_{IN}$ , 100 V / div.  
 Lower:  $I_{IN}$ , 2 A / div., 5 ms / div.

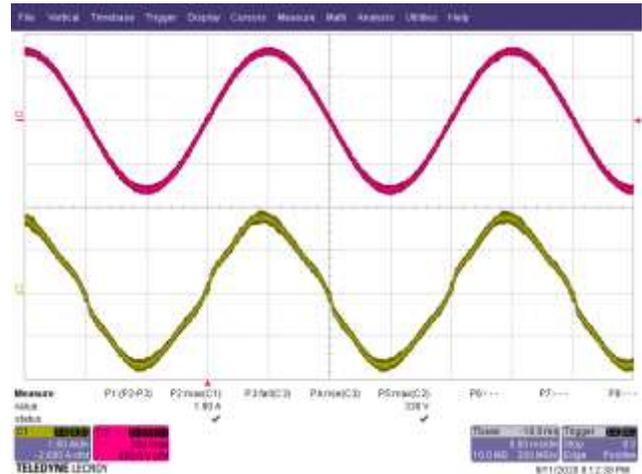


**Figure 24** – 115 VAC, 100% Load.  
 Upper:  $V_{IN}$ , 100 V / div.  
 Lower:  $I_{IN}$ , 2 A / div., 5 ms / div.

### 12.2 Input Current at 230 VAC and 50 Hz



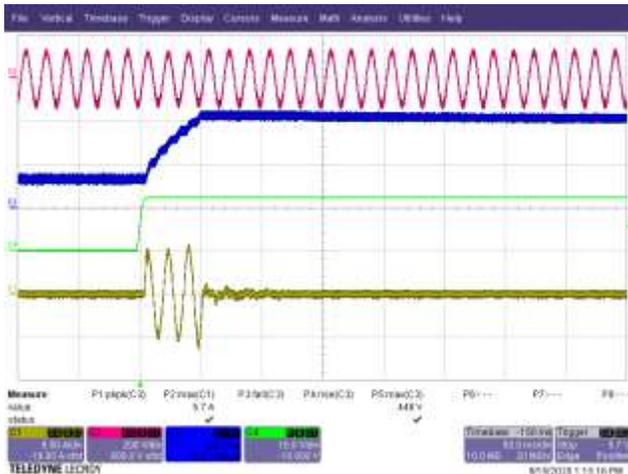
**Figure 25** – 230 VAC, 50% Load.  
 Upper:  $V_{IN}$ , 200 V / div.  
 Lower:  $I_{IN}$ , 1 A / div., 5 ms / div.



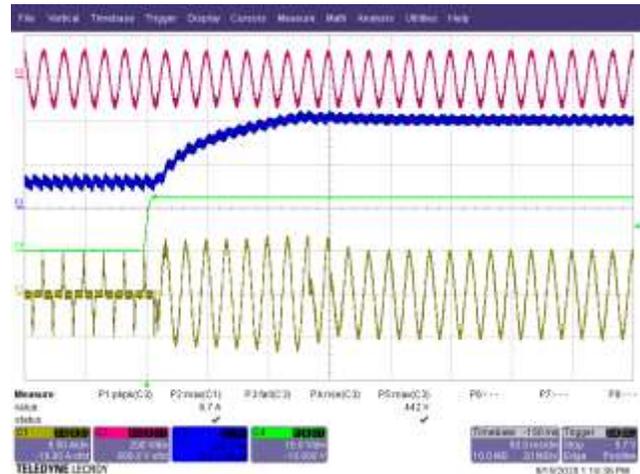
**Figure 26** – 230 VAC, 100% Load.  
 Upper:  $V_{IN}$ , 200 V / div.  
 Lower:  $I_{IN}$ , 1 A / div., 5 ms / div.

### 12.3 Start-up Waveforms

#### 12.3.1 90 VAC and 60 Hz

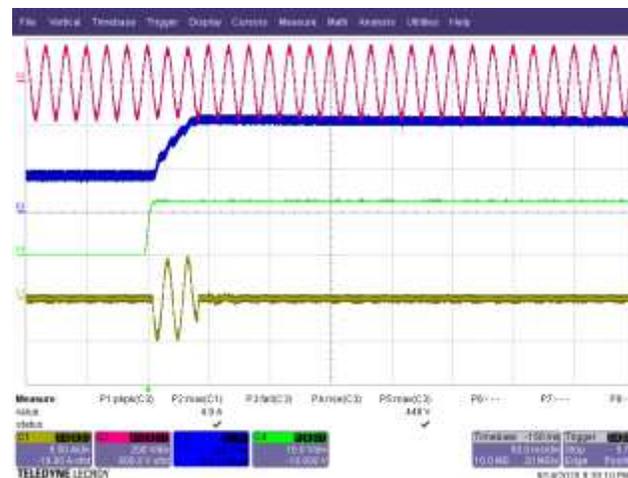


**Figure 27** – 90 VAC, No-Load.  
 Upper:  $V_{IN}$ , 200 V / div.  
 Second:  $V_{OUT}$ , 200 V / div.  
 Third:  $V_{aux}$ , 10 V / div.  
 Lower:  $I_{IN}$ , 5 A / div., 50 ms / div.

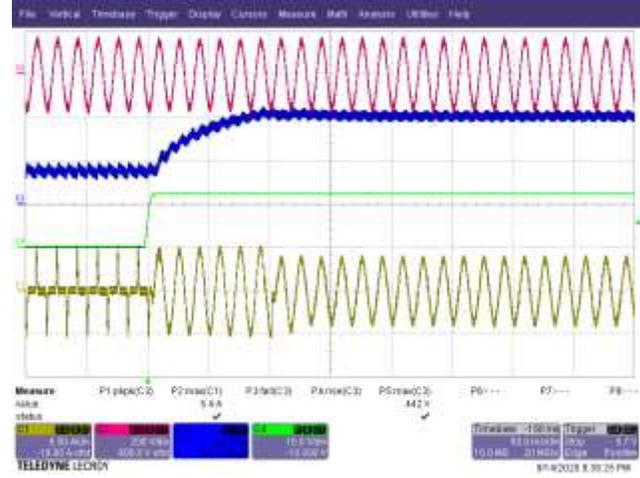


**Figure 28** – 90 VAC, Full Load.  
 Upper:  $V_{IN}$ , 200 V / div.  
 Second:  $V_{OUT}$ , 200 V / div.  
 Third:  $V_{aux}$ , 10 V / div.  
 Lower:  $I_{IN}$ , 5 A / div., 50 ms / div.

#### 12.3.2 115 VAC and 60 Hz

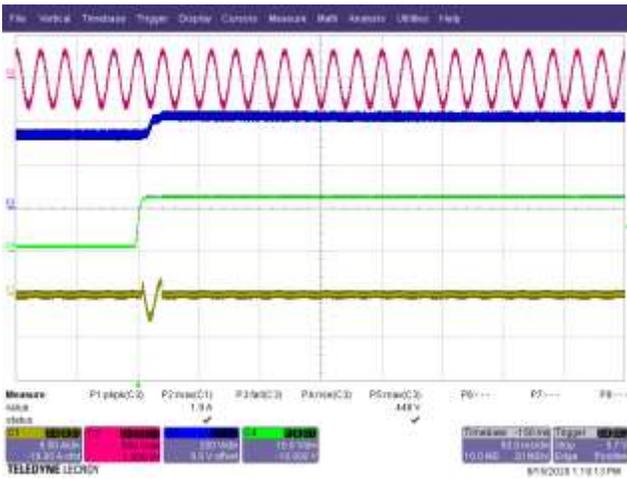


**Figure 29** – 115 VAC, No-Load.  
 Upper:  $V_{IN}$ , 200 V / div.  
 Second:  $V_{OUT}$ , 200 V / div.  
 Third:  $V_{aux}$ , 10 V / div.  
 Lower:  $I_{IN}$ , 5 A / div., 50 ms / div.

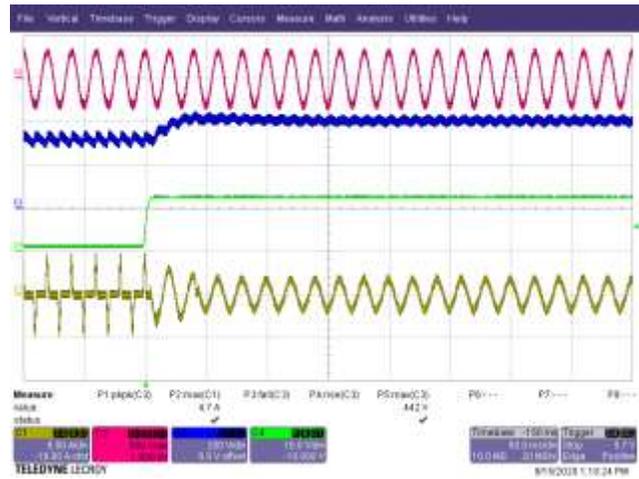


**Figure 30** – 115 VAC, Full Load.  
 Upper:  $V_{IN}$ , 200 V / div.  
 Second:  $V_{OUT}$ , 200 V / div.  
 Third:  $V_{aux}$ , 10 V / div.  
 Lower:  $I_{IN}$ , 5 A / div., 50 ms / div.

12.3.3 230 VAC and 50 Hz

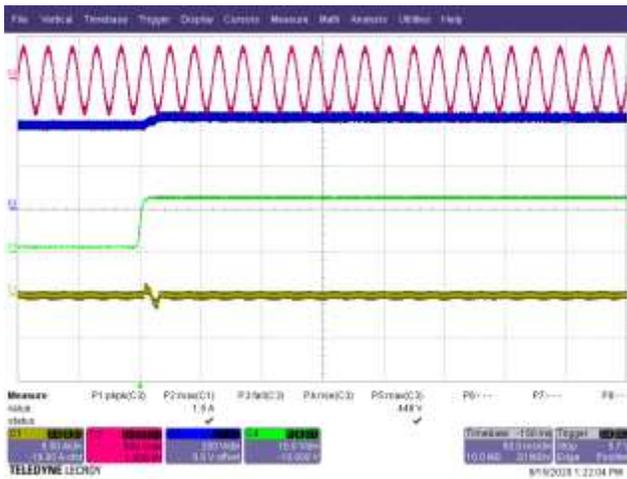


**Figure 31** – 230 VAC, No-Load.  
 Upper:  $V_{IN}$ , 500 V / div.  
 Second:  $V_{OUT}$ , 200 V / div.  
 Third:  $V_{aux}$ , 10 V / div.  
 Lower:  $I_{IN}$ , 5 A / div., 50 ms / div.

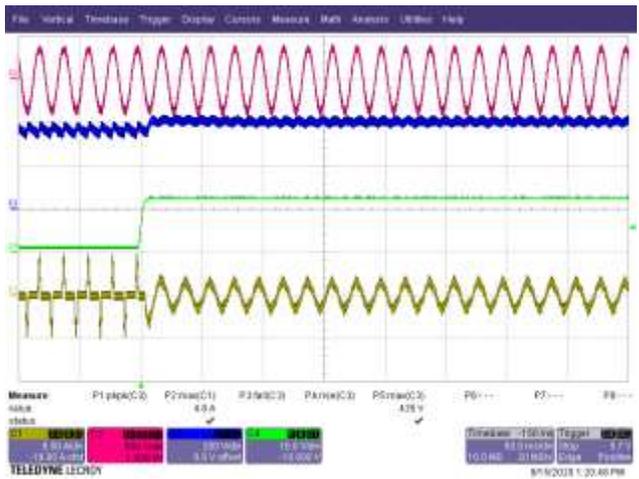


**Figure 32** – 230 VAC, Full Load.  
 Upper:  $V_{IN}$ , 500 V / div.  
 Second:  $V_{OUT}$ , 200 V / div.  
 Third:  $V_{aux}$ , 10 V / div.  
 Lower:  $I_{IN}$ , 5 A / div., 50 ms / div.

12.3.4 264 VAC and 50 Hz



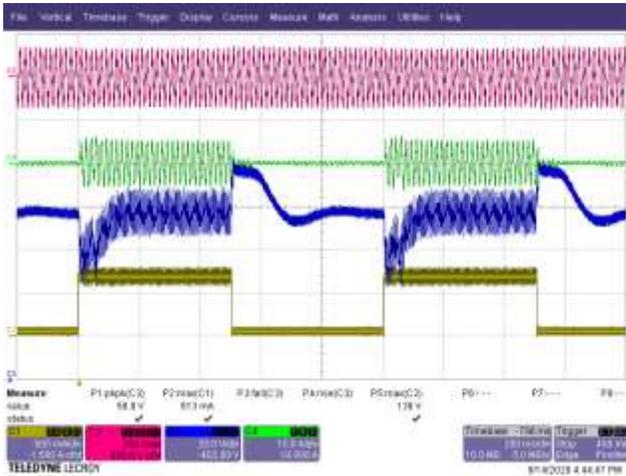
**Figure 33** – 264 VAC, No-Load.  
 Upper:  $V_{IN}$ , 500 V / div.  
 Second:  $V_{OUT}$ , 200 V / div.  
 Third:  $V_{aux}$ , 10 V / div.  
 Lower:  $I_{IN}$ , 5 A / div., 50 ms / div.



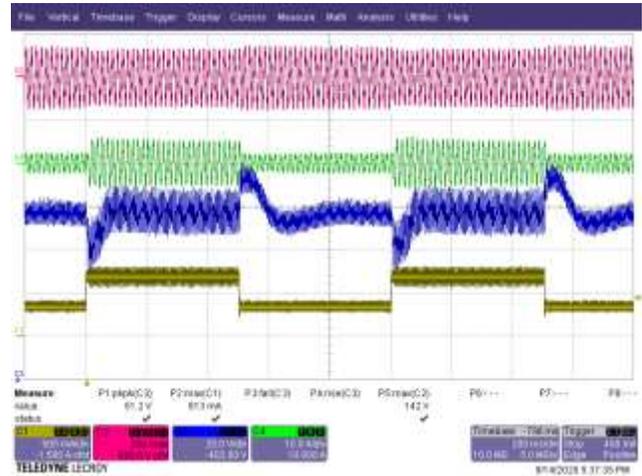
**Figure 34** – 264 VAC, Full Load.  
 Upper:  $V_{IN}$ , 500 V / div.  
 Second:  $V_{OUT}$ , 200 V / div.  
 Third:  $V_{aux}$ , 10 V / div.  
 Lower:  $I_{IN}$ , 5 A / div., 50 ms / div.

## 12.4 Load Transient Response

### 12.4.1 90 VAC, 60 Hz

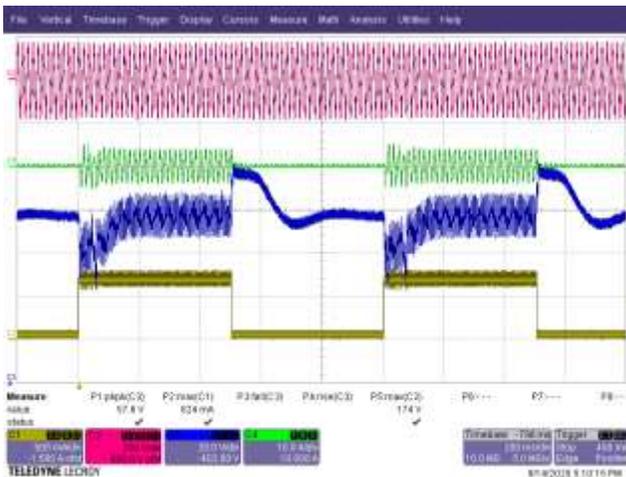


**Figure 35** – Transient Response, 90 VAC, 10-100-10% Load Step.  
 Upper:  $V_{IN}$ , 200 V / div.  
 Second:  $I_{IN}$ , 10 A / div.  
 Third:  $V_{OUT}$  (DC Coupled), 20 V / div.  
 Lower:  $I_{OUT}$ , 0.5 A / div., 200 ms / div.

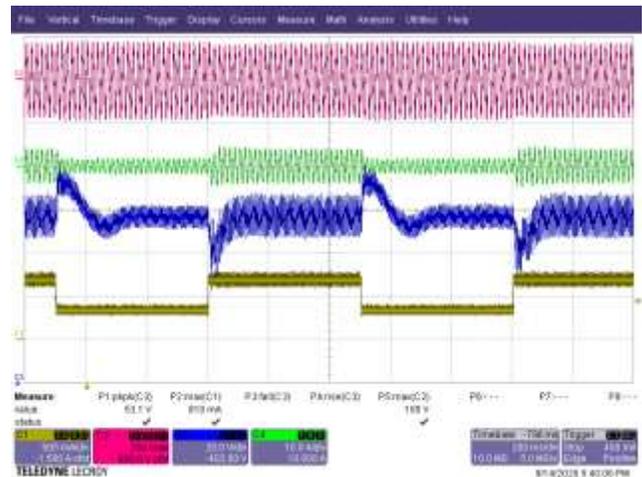


**Figure 36** – Transient Response, 90 VAC, 50-100-50% Load Step.  
 Upper:  $V_{IN}$ , 200 V / div.  
 Second:  $I_{IN}$ , 10 A / div.  
 Third:  $V_{OUT}$  (DC Coupled), 20 V / div.  
 Lower:  $I_{OUT}$ , 0.5 A / div., 200 ms / div.

### 12.4.2 115 VAC, 60 Hz

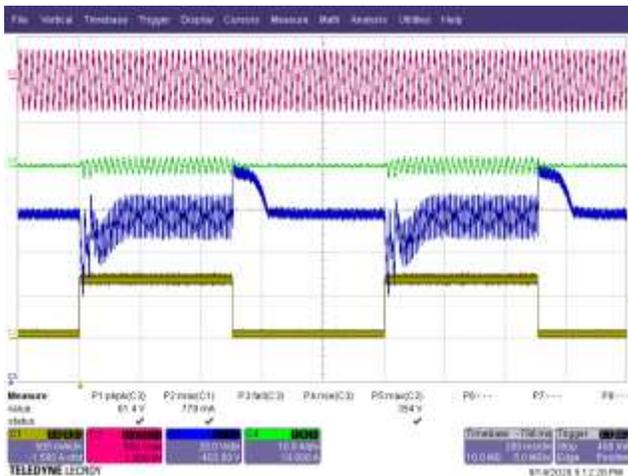


**Figure 37** – Transient Response, 115 VAC, 10-100-10% Load Step.  
 Upper:  $V_{IN}$ , 200 V / div.  
 Second:  $I_{IN}$ , 10 A / div.  
 Third:  $V_{OUT}$  (DC Coupled), 20 V / div.  
 Lower:  $I_{OUT}$ , 0.5 A / div., 200 ms / div.

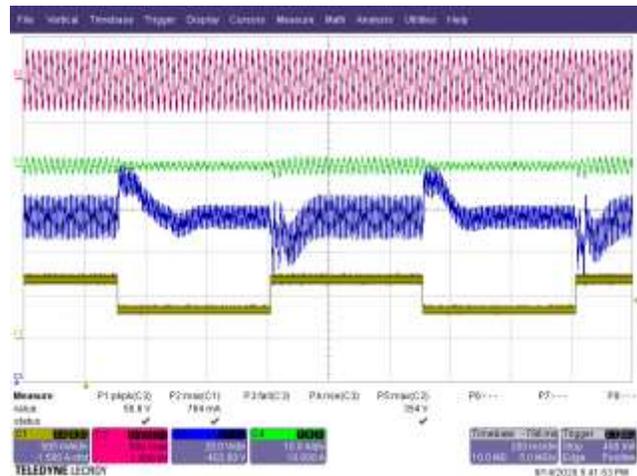


**Figure 38** – Transient Response, 115 VAC, 50-100-50% Load Step.  
 Upper:  $V_{IN}$ , 200 V / div.  
 Second:  $I_{IN}$ , 10 A / div.  
 Third:  $V_{OUT}$  (DC Coupled), 20 V / div.  
 Lower:  $I_{OUT}$ , 0.5 A / div., 200 ms / div.

12.4.3 230 VAC, 50 Hz

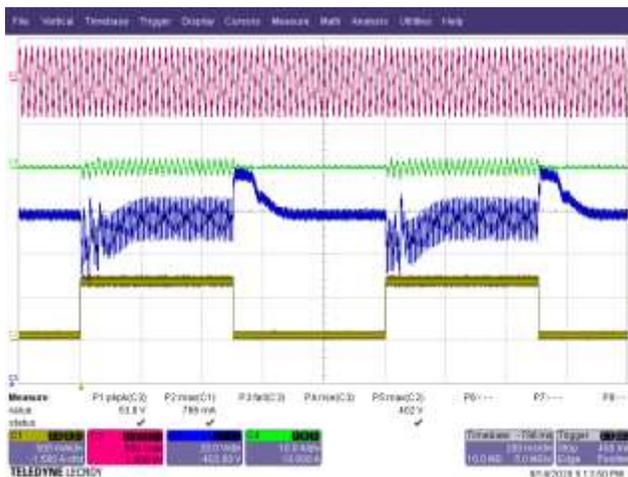


**Figure 39** – Transient Response, 230 VAC, 10-100-10% Load Step.  
 Upper:  $V_{IN}$ , 500 V / div.  
 Second:  $I_{IN}$ , 10 A / div.  
 Third:  $V_{OUT}$  (DC Coupled), 20 V / div.  
 Lower:  $I_{OUT}$ , 0.5 A / div., 200 ms / div.

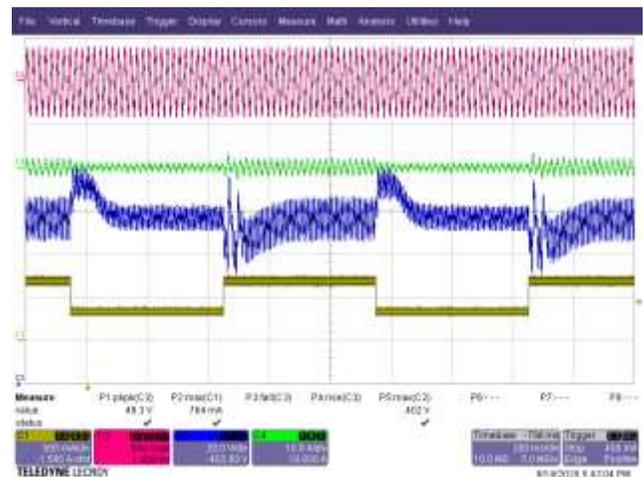


**Figure 40** – Transient Response, 230 VAC, 50-100-50% Load Step.  
 Upper:  $V_{IN}$ , 500 V / div.  
 Second:  $I_{IN}$ , 10 A / div.  
 Third:  $V_{OUT}$  (DC Coupled), 20 V / div.  
 Lower:  $I_{OUT}$ , 0.5 A / div., 200 ms / div.

12.4.4 264 VAC, 50 Hz



**Figure 41** – Transient Response, 264 VAC, 10-100-10% Load Step.  
 Upper:  $V_{IN}$ , 500 V / div.  
 Second:  $I_{IN}$ , 10 A / div.  
 Third:  $V_{OUT}$  (DC Coupled), 20 V / div.  
 Lower:  $I_{OUT}$ , 0.5 A / div., 200 ms / div.

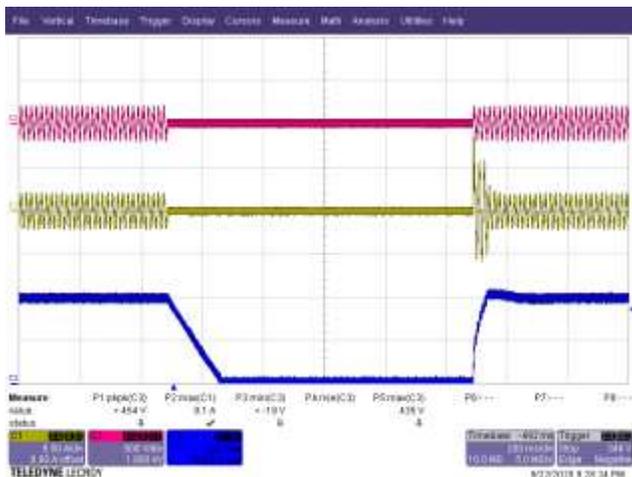


**Figure 42** – Transient Response, 264 VAC, 50-100-50% Load Step.  
 Upper:  $V_{IN}$ , 500 V / div.  
 Second:  $I_{IN}$ , 10 A / div.  
 Third:  $V_{OUT}$  (DC Coupled), 20 V / div.  
 Lower:  $I_{OUT}$ , 0.5 A / div., 200 ms / div.

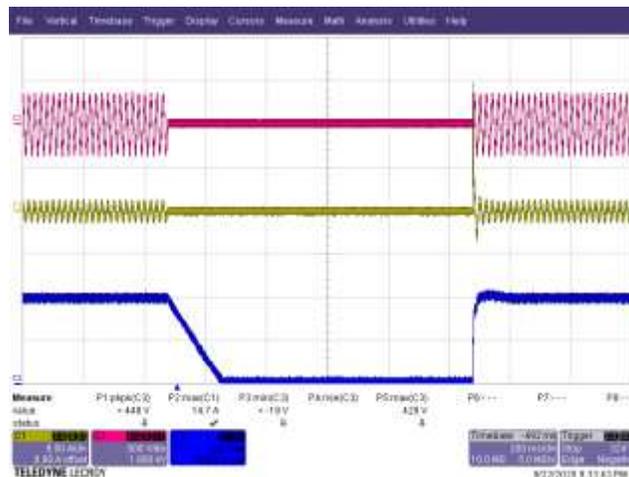
## 12.5 Line Dropout

### 12.5.1 1000 ms Line Dropout (115 VAC / 60 Hz and 230 VAC / 50 Hz)

#### 12.5.1.1 50% Load at Output

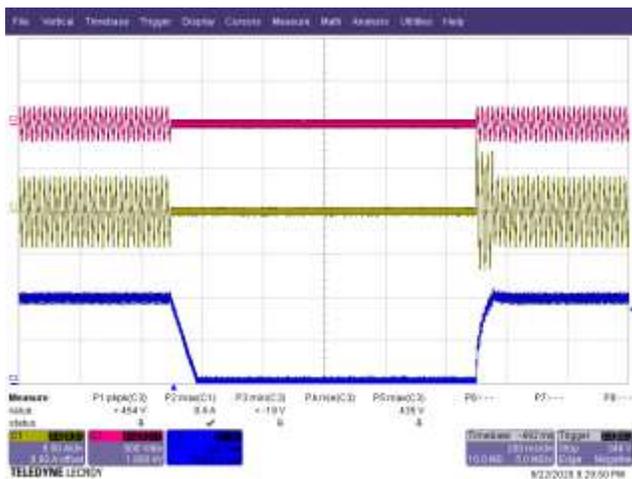


**Figure 43** – Line Dropout 115 VAC, 1000 ms.  
Upper:  $V_{IN}$ , 500 V / div.  
Middle:  $I_{IN}$ , 5 A / div.  
Lower:  $V_{OUT}$ , 200 V / div., 200 ms / div.

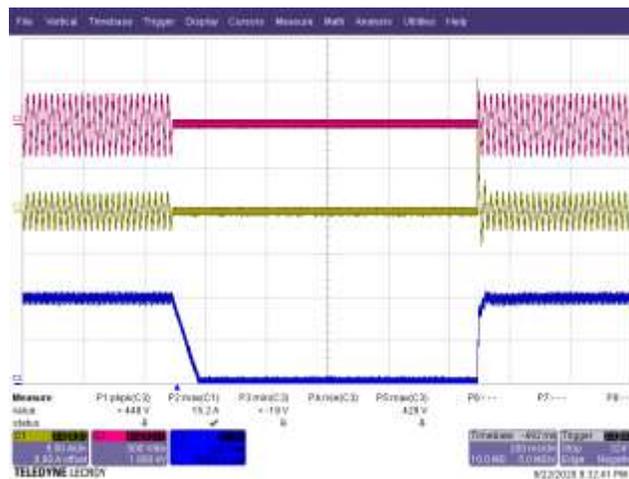


**Figure 44** – Line Dropout 230 VAC, 1000 ms.  
Upper:  $V_{IN}$ , 500 V / div.  
Middle:  $I_{IN}$ , 5 A / div.  
Lower:  $V_{OUT}$ , 200 V / div., 200 ms / div.

#### 12.5.1.2 Full Load at Output



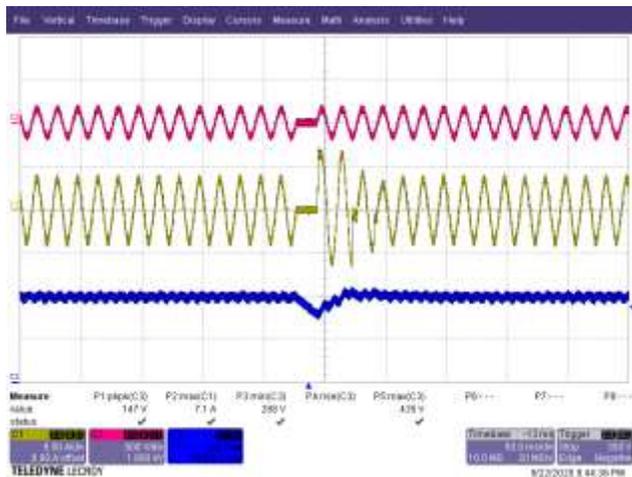
**Figure 45** – Line Dropout 115 VAC, 1000 ms.  
Upper:  $V_{IN}$ , 500 V / div.  
Middle:  $I_{IN}$ , 5 A / div.  
Lower:  $V_{OUT}$ , 200 V / div., 200 ms / div.



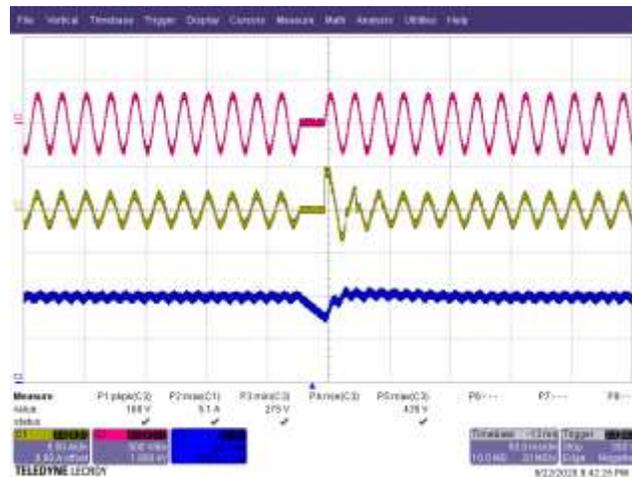
**Figure 46** – Line Dropout 230 VAC, 1000 ms.  
Upper:  $V_{IN}$ , 500 V / div.  
Middle:  $I_{IN}$ , 5 A / div.  
Lower:  $V_{OUT}$ , 200 V / div., 200 ms / div.

12.5.2 One Cycle Line Dropout (115 VAC / 60 Hz and 230 VAC / 50 Hz)

12.5.2.1 Full Load at Output



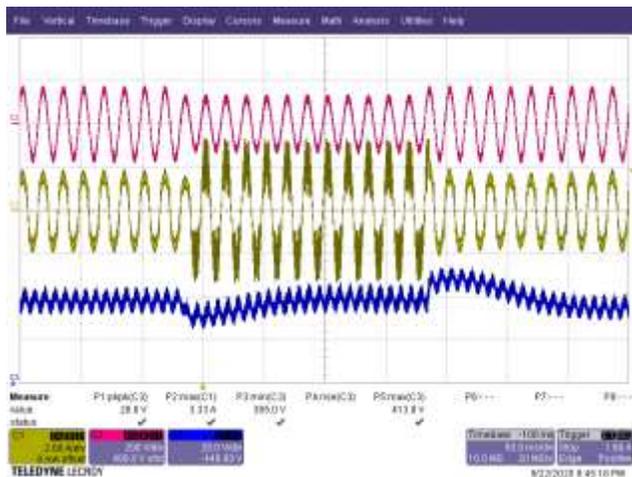
**Figure 47** – Line Dropout 115 VAC, 60 Hz.  
 Upper:  $V_{IN}$ , 500 V / div.  
 Middle:  $I_{IN}$ , 5 A / div.  
 Lower:  $V_{OUT}$ , 200 V / div., 50 ms / div.



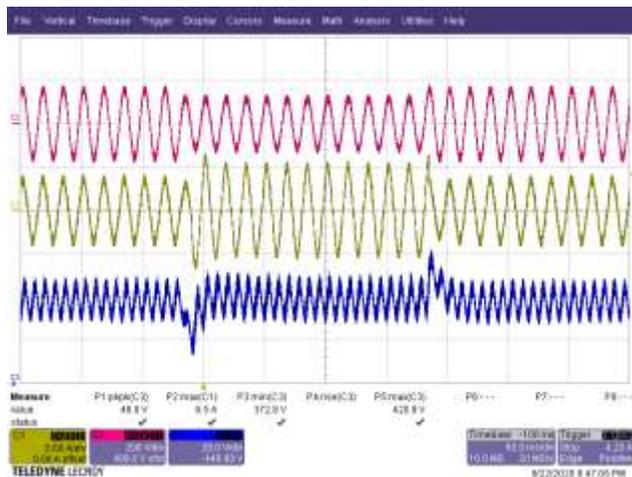
**Figure 48** – Line Dropout 230 VAC, 50 Hz.  
 Upper:  $V_{IN}$ , 500 V / div.  
 Middle:  $I_{IN}$ , 5 A / div.  
 Lower:  $V_{OUT}$ , 200 V / div., 50 ms / div.

12.6 *Input Line Step*

12.6.1 Line Sag (115 VAC ~ 85 VAC ~ 115 VAC, 60 Hz)

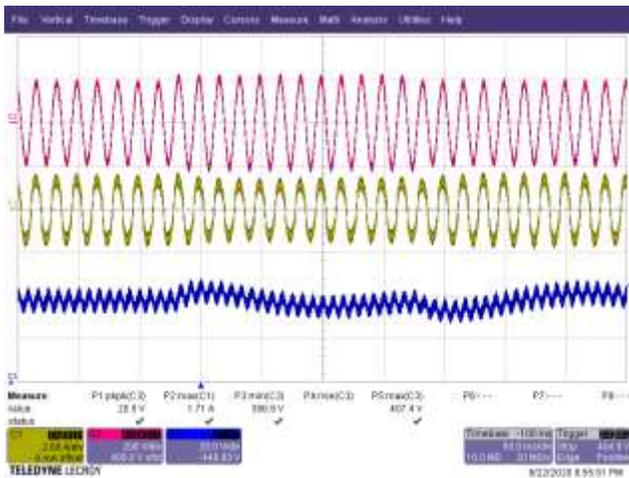


**Figure 49** – Line Sag 115 VAC, 50% Load.  
 Upper:  $V_{IN}$ , 200 V / div.  
 Middle:  $I_{IN}$ , 2 A / div.  
 Lower:  $V_{OUT}$  (DC Coupled), 20 V / div., 50 ms / div.

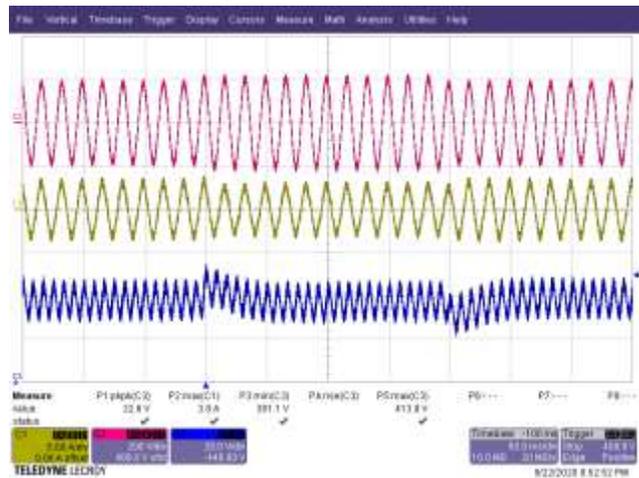


**Figure 50** – Line Sag 115 VAC, 100% Load.  
 Upper:  $V_{IN}$ , 200 V / div.  
 Middle:  $I_{IN}$ , 5 A / div.  
 Lower:  $V_{OUT}$  (DC Coupled), 20 V / div., 50 ms / div.

12.6.2 Line Swell (132 VAC ~ 147 VAC ~ 132 VAC, 60 Hz)

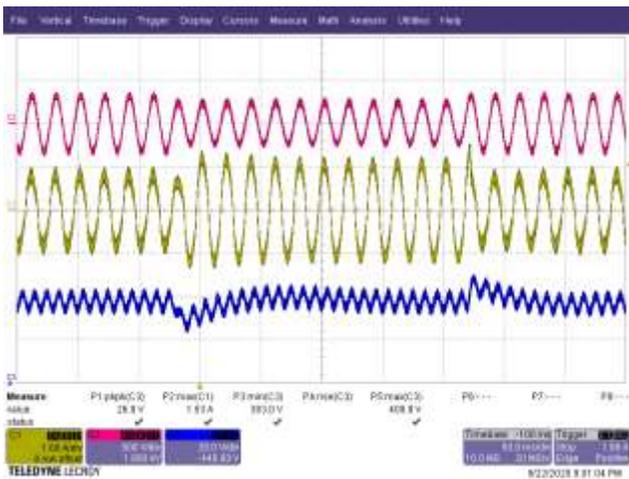


**Figure 51** – Line Surge 132 VAC, 50% Load.  
 Upper:  $V_{IN}$ , 200 V / div.  
 Middle:  $I_{IN}$ , 2 A / div.  
 Lower:  $V_{OUT}$  (DC Coupled), 20 V / div.,  
 50 ms / div.

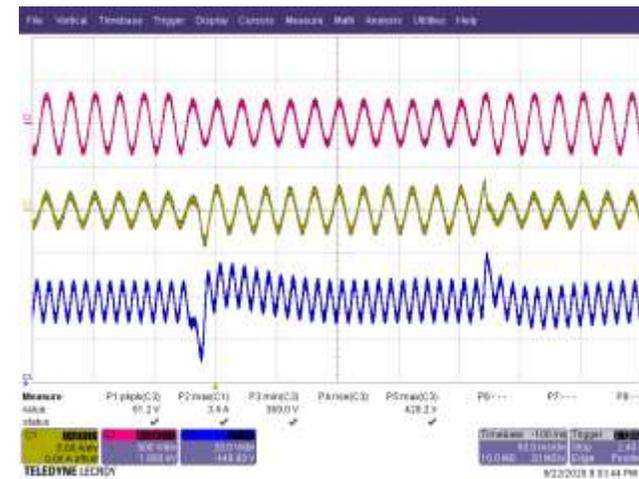


**Figure 52** – Line Surge 132 VAC, 100% Load.  
 Upper:  $V_{IN}$ , 200 V / div.  
 Middle:  $I_{IN}$ , 5 A / div.  
 Lower:  $V_{OUT}$  (DC Coupled), 20 V / div.,  
 50 ms / div.

12.6.3 Line Sag (230 VAC ~ 170 VAC ~ 230 VAC, 50 Hz)

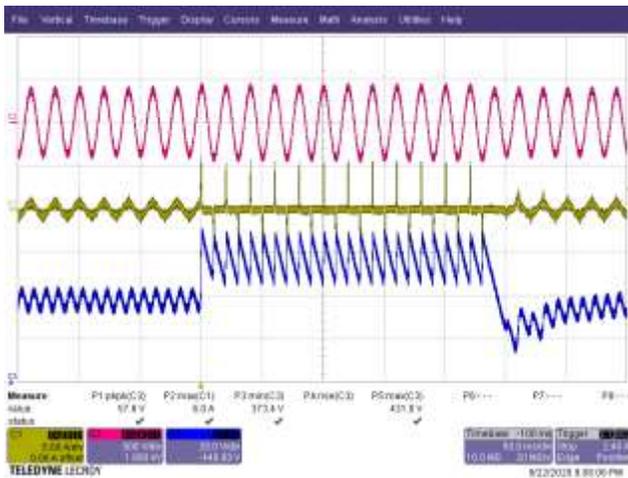


**Figure 53** – Line Sag 230 VAC, 50% Load.  
 Upper:  $V_{IN}$ , 500 V / div.  
 Middle:  $I_{IN}$ , 1 A / div.  
 Lower:  $V_{OUT}$  (DC Coupled), 20 V / div.,  
 50 ms / div.

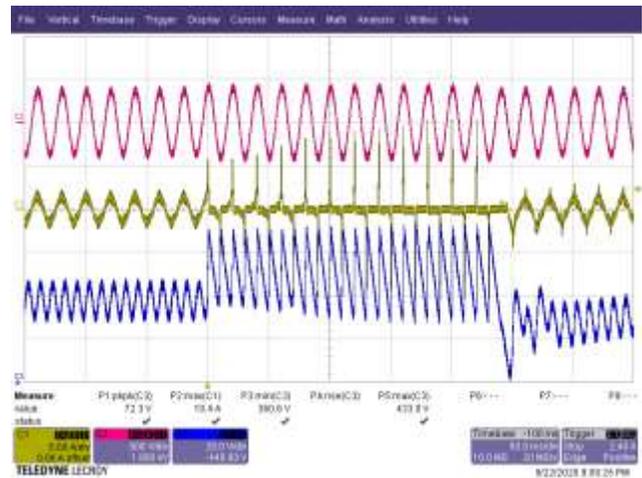


**Figure 54** – Line Sag 230 VAC, 100% Load.  
 Upper:  $V_{IN}$ , 500 V / div.  
 Middle:  $I_{IN}$ , 5 A / div.  
 Lower:  $V_{OUT}$  (DC Coupled), 20 V / div.,  
 50 ms / div.

12.6.4 Line Swell (264 VAC ~ 293 VAC ~ 264 VAC, 50 Hz)



**Figure 55** – Line Surge 264 VAC, 50% Load.  
 Upper:  $V_{IN}$ , 500 V / div.  
 Middle:  $I_{IN}$ , 5 A / div.  
 Lower:  $V_{OUT}$  (DC Coupled), 20 V / div.,  
 50 ms / div.

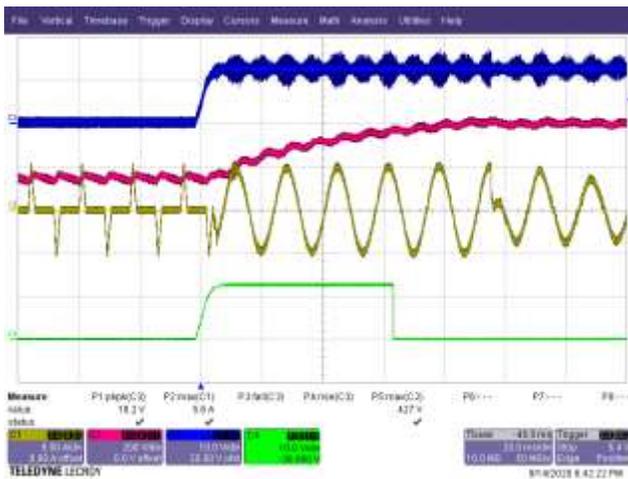


**Figure 56** – Line Surge 264 VAC, 100% Load.  
 Upper:  $V_{IN}$ , 500 V / div.  
 Middle:  $I_{IN}$ , 5 A / div.  
 Lower:  $V_{OUT}$  (DC Coupled), 20 V / div., 50  
 ms / div.

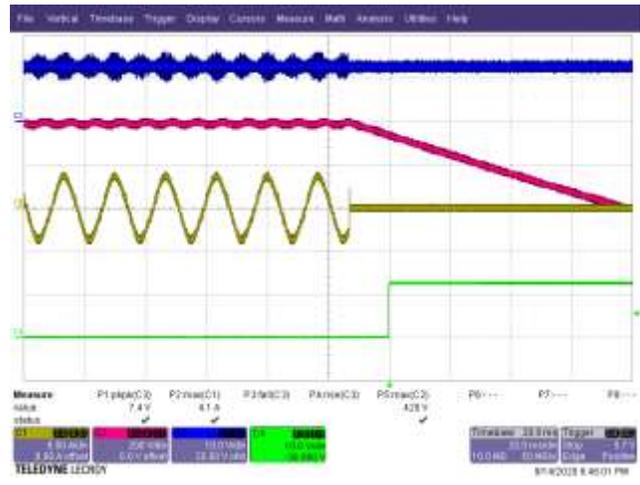
### 12.7 Power Good (PG)

Power Good (PG) waveforms were measured at startup and shutdown with the PG output optocoupler collector (J2-2) tied to the VCC (J4-1) via a 10 kΩ resistor. The PG optocoupler emitter was tied to the VCC return (J4-2).

#### 12.7.1 115 VAC and 60 Hz

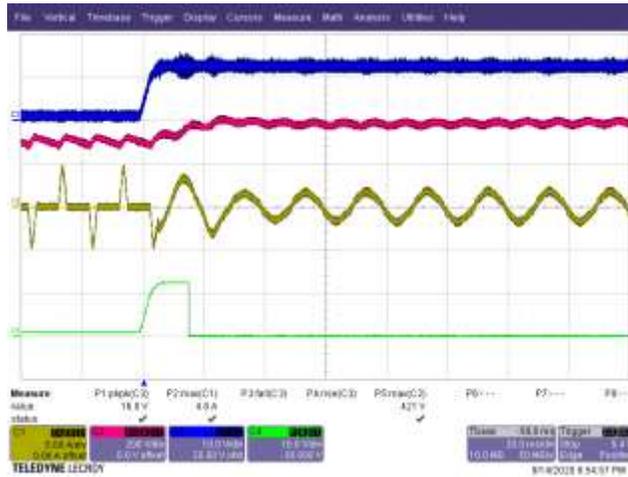


**Figure 57** – 115 VAC, Full Load,  $V_{OUT}$  Rising Edge.  
 1<sup>st</sup>:  $V_{CC}$ , 10 V / div.  
 2<sup>nd</sup>:  $V_{OUT}$ , 200 V / div.  
 3<sup>rd</sup>:  $I_{IN}$ , 5 A / div.  
 4<sup>th</sup>: PG, 10 V / div, 20 ms / div.

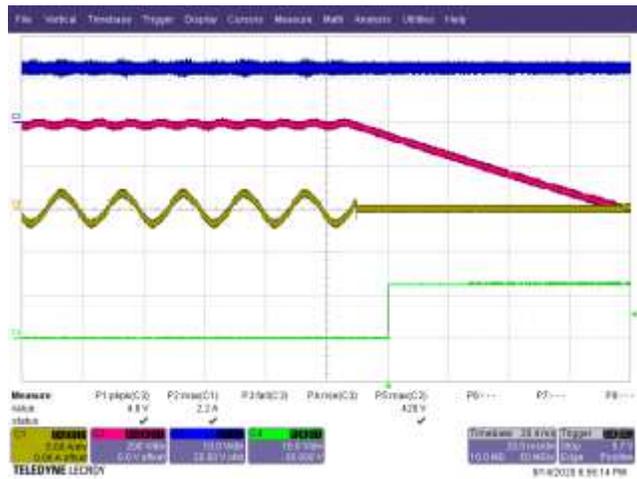


**Figure 58** – 115 VAC, Full Load,  $V_{OUT}$  Falling Edge.  
 1<sup>st</sup>:  $V_{CC}$ , 10 V / div.  
 2<sup>nd</sup>:  $V_{OUT}$ , 200 V / div.  
 3<sup>rd</sup>:  $I_{IN}$ , 5 A / div.  
 4<sup>th</sup>: PG, 10 V / div, 20 ms / div.

#### 12.7.2 230 VAC and 50 Hz



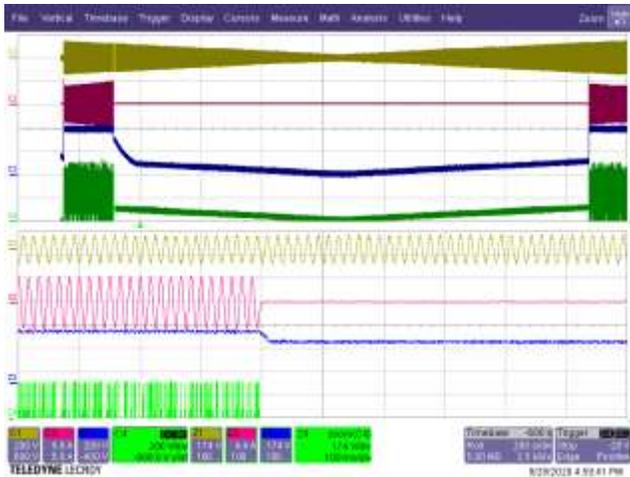
**Figure 59** – 230 VAC, 100% Load,  $V_{out}$  Rising Edge.  
 1<sup>st</sup>:  $V_{CC}$ , 10 V / div.  
 2<sup>nd</sup>:  $V_{OUT}$ , 200 V / div.  
 3<sup>rd</sup>:  $I_{IN}$ , 5 A / div.  
 4<sup>th</sup>: PG, 10 V / div, 20 ms / div.



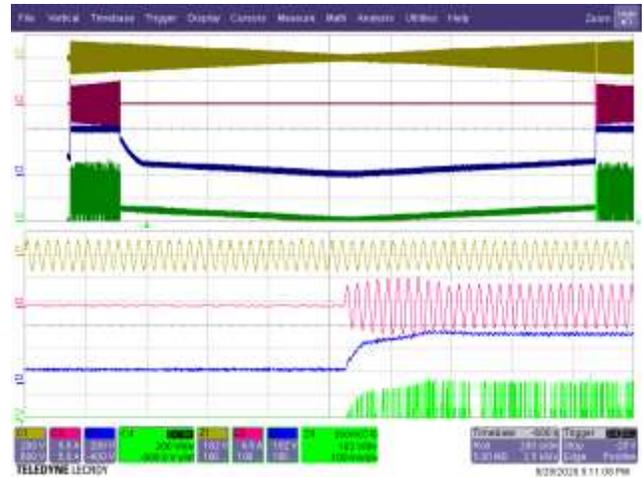
**Figure 60** – 230 VAC, 100% Load,  $V_{out}$  Falling Edge.  
 1<sup>st</sup>:  $V_{CC}$ , 10 V / div.  
 2<sup>nd</sup>:  $V_{OUT}$ , 200 V / div.  
 3<sup>rd</sup>:  $I_{IN}$ , 5 A / div.  
 4<sup>th</sup>: PG, 10 V / div, 20 ms / div.

**Note:** For Figures 56 and 58, input AC voltage was turned off to verify PG transition threshold.





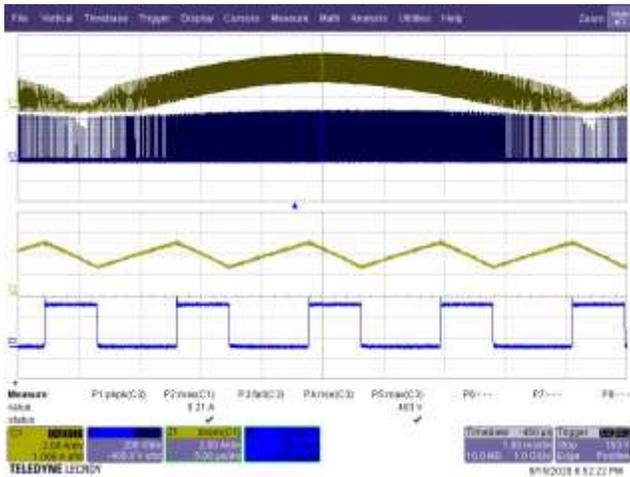
**Figure 62** – Brown-out with 100% Load, Zoom-in  
 Upper (Yellow):  $V_{IN}$ , 200 V / div.  
 Middle (Red):  $I_{IN}$ , 5 A / div.  
 Third (Blue):  $V_{OUT}$ , 200 V / div.  
 Lower (Green):  $V_{DS}$ , 200 V / div. Zoom in 100 ms / div.



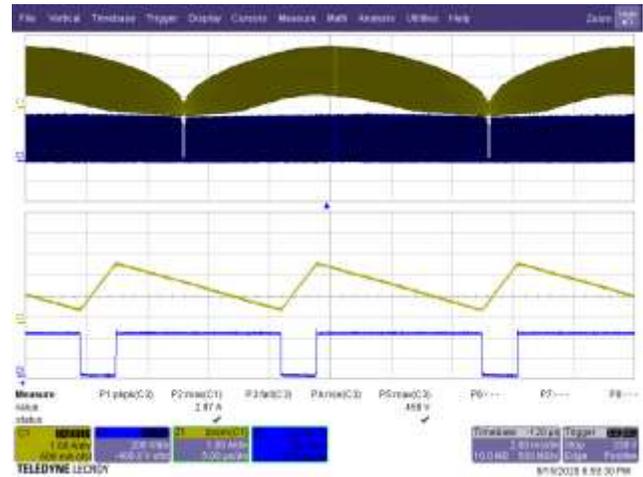
**Figure 63** – Brown-in with 100% Load, Zoom-in  
 Upper (Yellow):  $V_{IN}$ , 200 V / div.  
 Middle (Red):  $I_{IN}$ , 5 A / div.  
 Third (Blue):  $V_{OUT}$ , 200 V / div.  
 Lower (Green):  $V_{DS}$ , 200 V / div, Zoom in 100 ms / div.

### 12.8.3 Drain Voltage and Inductor Current

Since PFC output diode is integrated into the package, there is no direct access of the MOSFET drain current. Therefore inductor current was measured at jumper JP1 location by replacing JP1 with a short wire loop in order to insert the current probe. The Drain voltage was measured at the DRAIN and SOURCE pins of IC U1.



**Figure 64** – Input Voltage 115 VAC, 100% Load.  
 Upper:  $I_{INDUCTOR}$ , 2 A / div.  
 Lower:  $V_{DRAIN}$ , 200 V / div., 1 ms / div.  
 Zoom Upper:  $I_{INDUCTOR}$ , 2 A / div.  
 Zoom Lower:  $V_{DRAIN}$ , 200 V / div., 5  $\mu$ s / div.



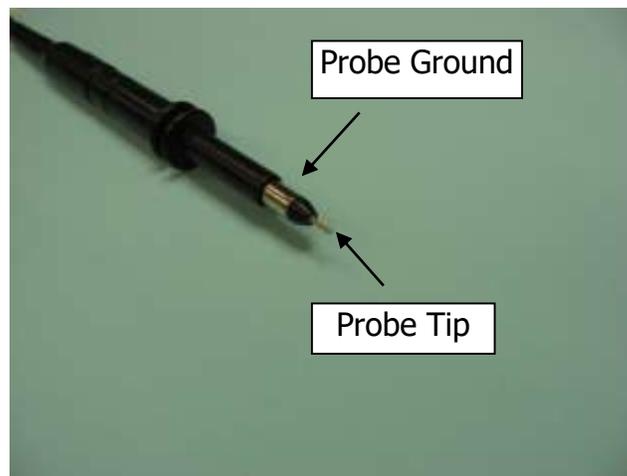
**Figure 65** – Input Voltage 230 VAC, 100% Load.  
 Upper:  $I_{INDUCTOR}$ , 1 A / div.  
 Lower:  $V_{DRAIN}$ , 200 V / div., 2 ms / div.  
 Zoom Upper:  $I_{INDUCTOR}$ , 1 A / div.  
 Zoom Lower:  $V_{DRAIN}$ , 200 V / div., 5  $\mu$ s / div.

## 12.9 *Output Ripple Measurements*

### 12.9.1 Ripple Measurement Technique

For DC output ripple measurements, a modified oscilloscope test probe must be utilized in order to reduce spurious signals due to pick up. Details of the probe modification are provided in the figures below.

The 4987BA probe adapter is affixed with one capacitor 0.02  $\mu$ F/1 kV ceramic disc type tied in parallel across the probe tip.

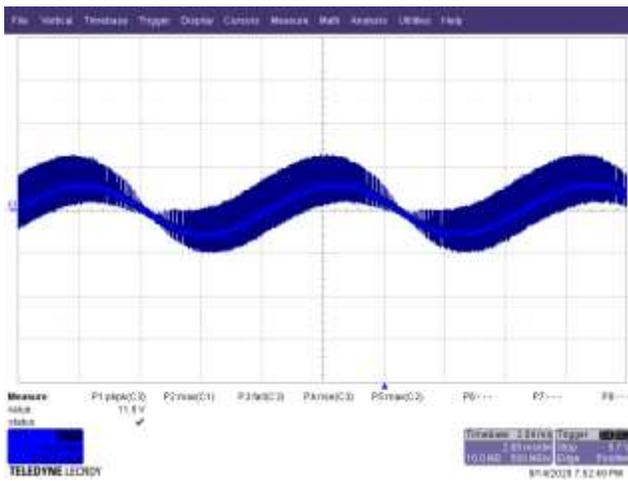


**Figure 66** – Oscilloscope Probe Prepared for Ripple Measurement (End cap and ground lead removed.)

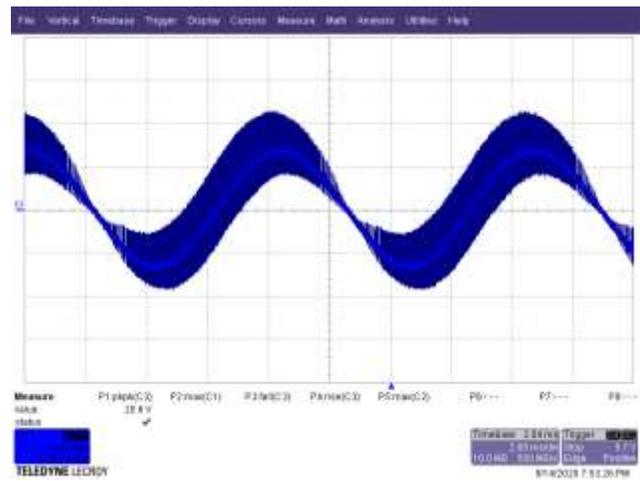


**Figure 67** – Oscilloscope Probe with Probe Master ([www.probemaster.com](http://www.probemaster.com)) 4987A BNC Adapter (Modified with wires for ripple measurement, and one parallel decoupling capacitor added.)

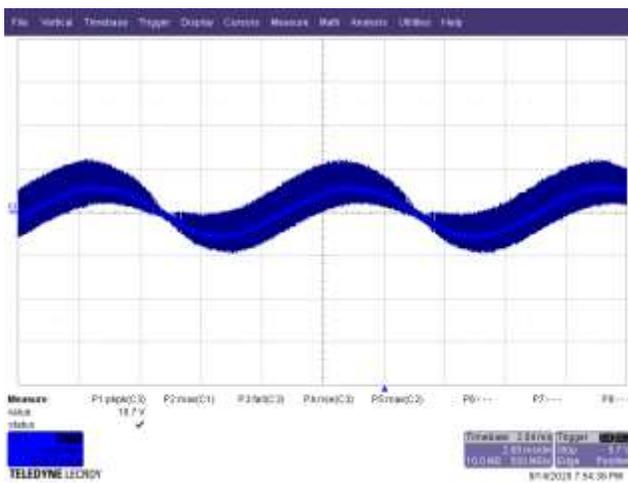
### 12.9.2 Measurement Results



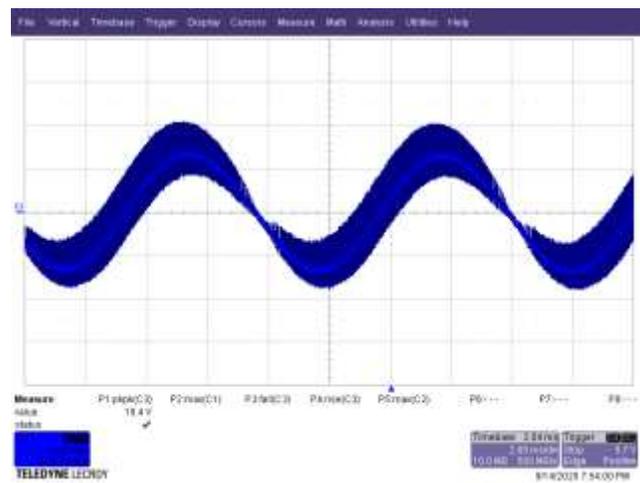
**Figure 68** – Ripple, 90 VAC, 50% Load.  
5 V / div., 2 ms / div.



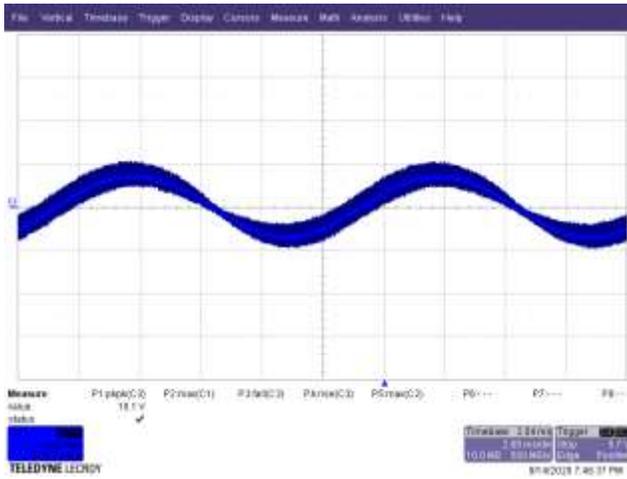
**Figure 69** – Ripple, 90 VAC, 100% Load.  
5 V / div., 2 ms / div.



**Figure 70** – Ripple, 115 VAC, 50% Load.  
5 V / div., 2 ms / div.



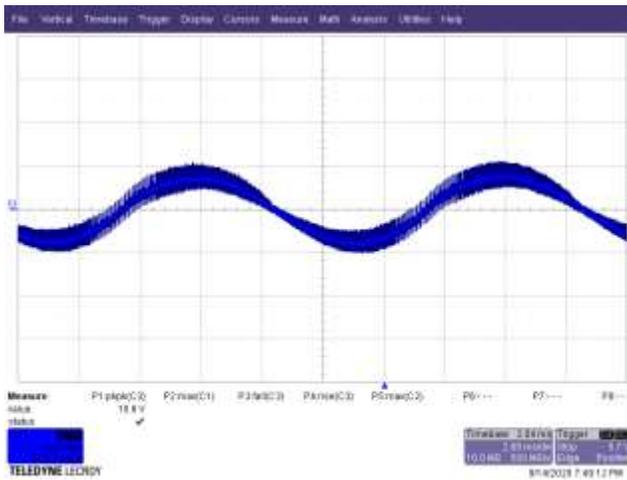
**Figure 71** – Ripple, 115 VAC, 100% Load.  
5 V / div., 2 ms / div.



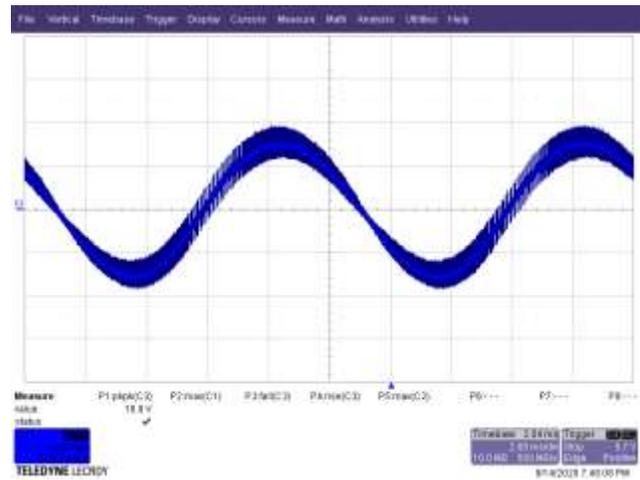
**Figure 72** – Ripple, 230 VAC, 50% Load.  
5 V / div., 2 ms / div.



**Figure 73** – Ripple, 230 VAC, 100% Load.  
5 V / div., 2 ms / div.



**Figure 74** – Ripple, 264 VAC, 50% Load.  
5 V / div., 2 ms / div.



**Figure 75** – Ripple, 264 VAC, 100% Load.  
5 V / div., 2 ms / div.

### 12.10 Gain-Phase Measurement Procedure and Results

- The PFC stage is supplied from an adjustable DC source for this test. Connect the circuit as shown in figure below. Open the top end of the feedback divider network and insert a  $100\ \Omega$ – $2\ \text{W}$  resistor in series as shown. The signal injected in the loop for gain–phase measurement will be injected across this resistor.
- Nodes A and B (two ends of the injection resistor) are connected to Channel 1 and Channel 2 of the frequency response analyzer using high voltage  $\times 100$  attenuator probes. GND leads of both probes are connected to output return as shown.
- The signal to be injected is isolated using the Bode–Box injection transformer model – 200–000 from Venable Industries.

#### Test Procedure:

- Adjust the input voltage to 150 VDC and confirm that the PFC output voltage is within regulation limits.
- Inject a signal from the frequency response analyzer.
- The injected signal can be seen in the output voltage ripple of the PFC.
- Plot the gain phase by sweeping the injected signal frequency from 2 Hz to 1000 Hz.
- Note: Due to HV bench supply limits, only 75% load is available at 150VDC

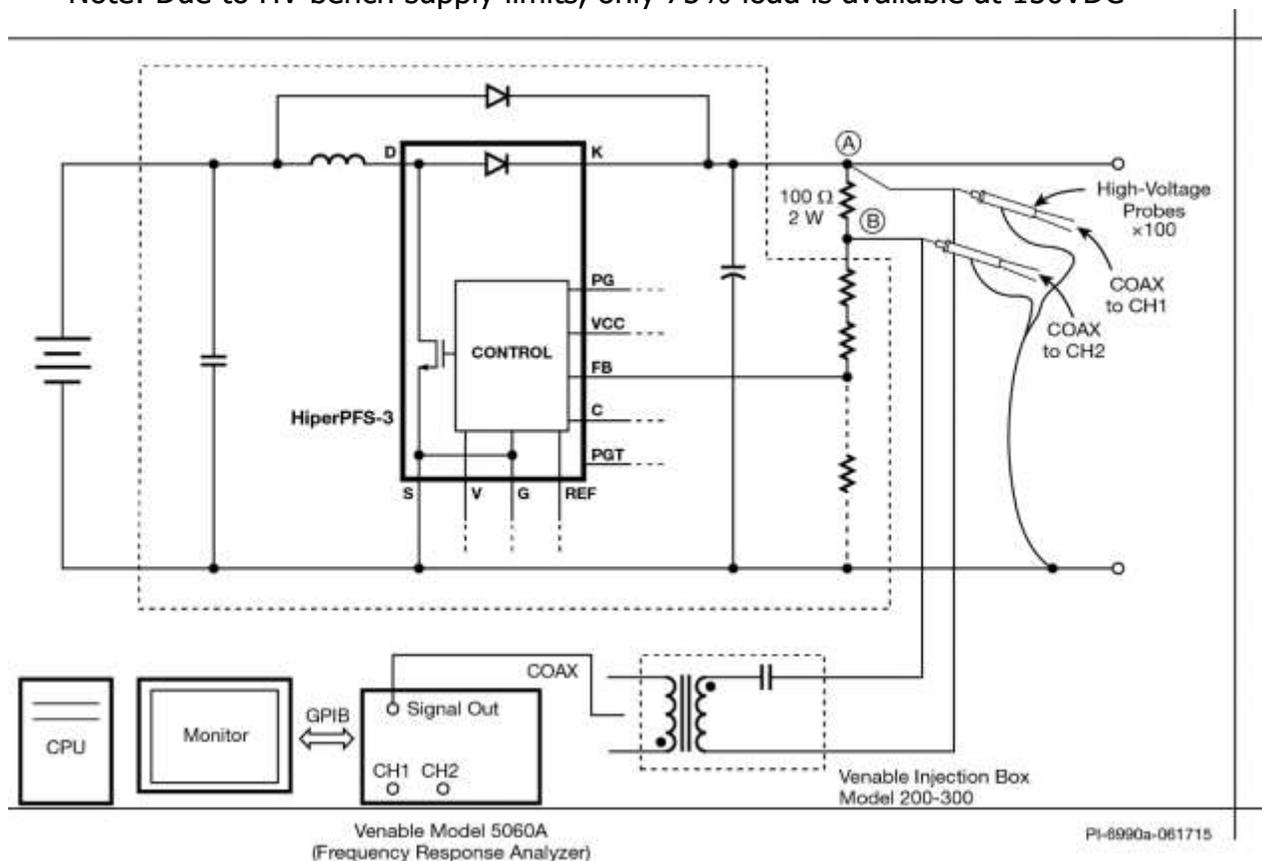
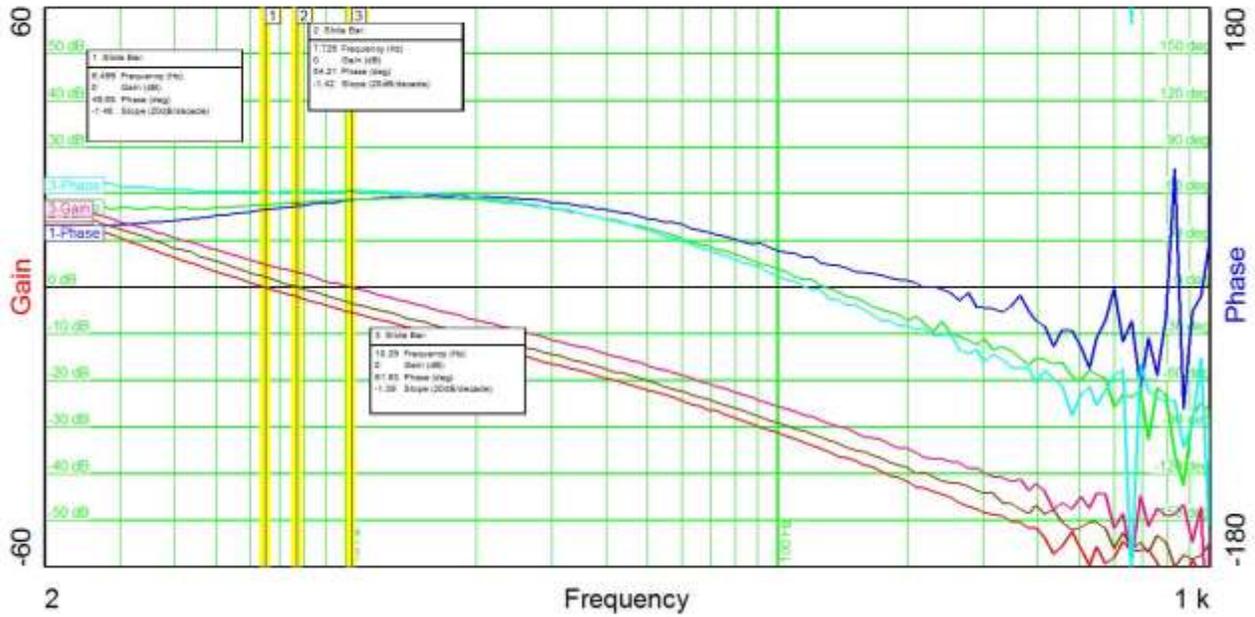
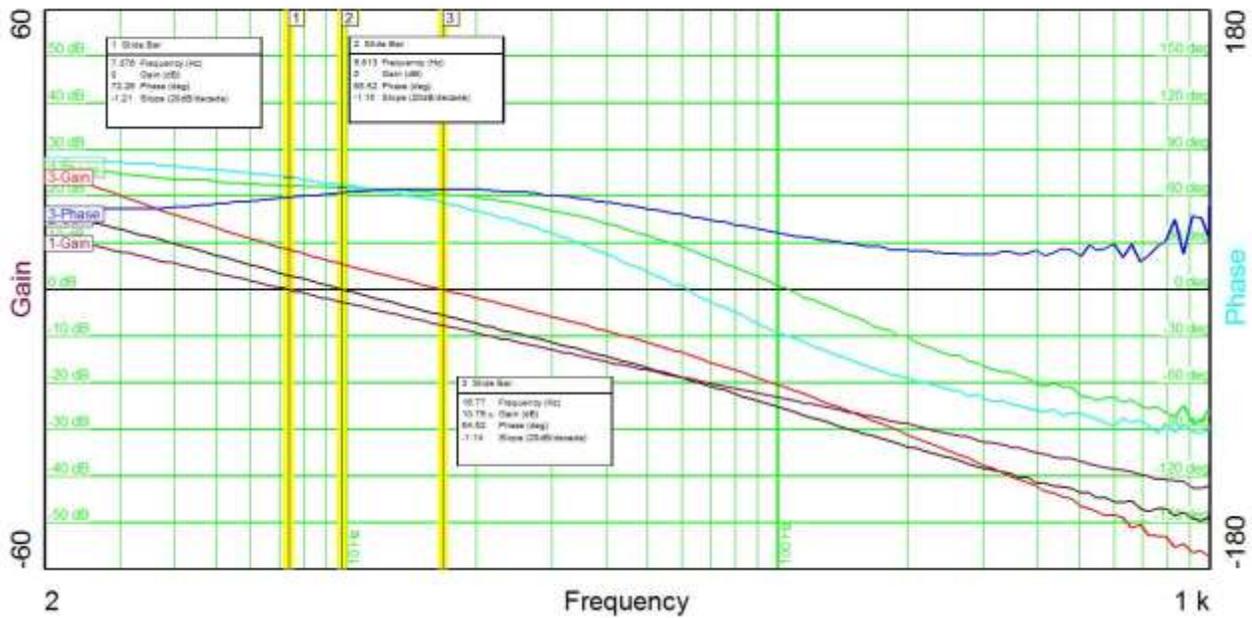


Figure 76 – System Test Set-up for Loop Gain-Phase Measurement.

12.10.1 Measured Bode Plots



**Figure 77** – Bode Plot with  $V_{IN} = 150$  VDC at 75%, 50% and 20% Load.  
 20% Load (Red/Blu) – Slide Bar #1 Gain Crossover, 6.5 Hz, Phase Margin 49.7°.  
 50% Load (Grn/Brn) – Slide Bar #2, Gain Crossover 7.7 Hz, Phase Margin 54.2°.  
 75% Load (Pnk/Aqua) – Slide Bar #3, Gain Crossover 10.3 Hz, Phase Margin 61.8°.



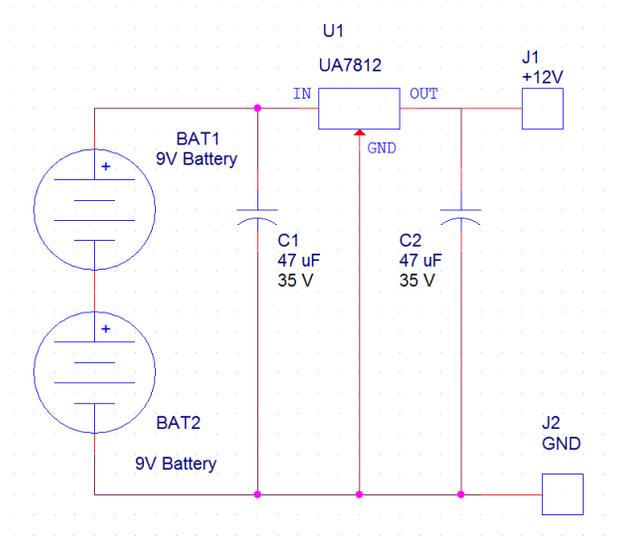
**Figure 78** – Bode Plot with  $V_{IN} = 300$  VDC at 100%, 50% and 20% Load.  
 20% Load (Red/Blu) – Slide Bar #1, Gain Crossover 16.8 Hz, Phase Margin 64.5°.  
 50% Load (Grn/Brn) – Slide Bar #2, Gain Crossover 9.8 Hz, Phase Margin 65.5°.  
 100% Load (Pnk/Pur) – Slide Bar #3, Gain Crossover 7.4 Hz, Phase Margin 72.3°.

### 13 Line Surge Test

Differential input line surge testing was completed on a single test unit to IEC61000-4-5. Input voltage was set at 230 VAC / 50 Hz. The UUT output was resistively loaded at full load and operation was verified following each surge event. The UUT was powered with a pair of 9V batteries connected in series, feeding an LM7812 IC regulator, as shown in Figure 78. A single-sided 0.062" thick copper-clad FR4 material was placed under the UUT, insulation side up, and with the copper side of the board connected to earth ground at the AC input connector. A green GaP LED with a 1k series resistor was connected between the collector of optocoupler U3 and the 12 V VCC supply, with the U3 emitter connected to ground. This served as an indication of continued supply operation by monitoring the "Power Good" function of the PFS-4.



**Figure 79** – Line Surge UUT Set-up.



**Figure 78** – 12V Aux Supply for Surge Testing.

13.1 *Differential Mode Surge*

AC Input Voltage (VAC)	Surge Voltage (kV)	Phase Angle (°)	Generator Impedance ( $\Omega$ )	Number of Strikes	Test Result
230	+2	0	2	10	PASS
230	-2	0	2	10	PASS
230	+2	90	2	10	PASS
230	-2	90	2	10	PASS
230	+2	180	2	10	PASS
230	-2	180	2	10	PASS
230	+2	270	2	10	PASS
230	-2	270	2	10	PASS

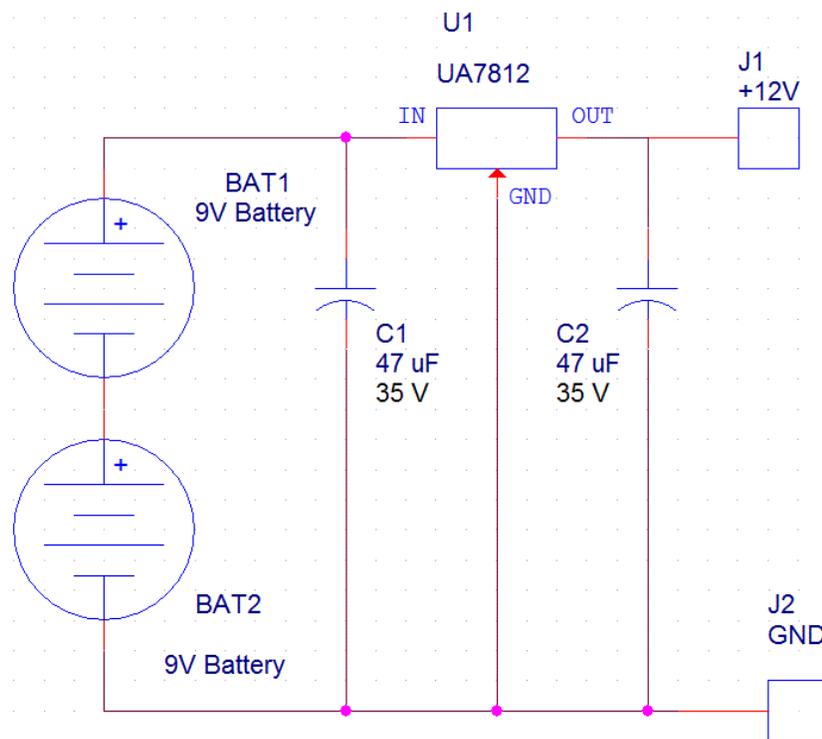
13.2 *Common Mode Surge*

AC Input Voltage (VAC)	Surge Voltage (kV)	Phase Angle (°)	Generator Impedance ( $\Omega$ )	Number of Strikes	Test Result
230	+3	0	12	10	PASS
230	-3	0	12	10	PASS
230	+3	90	12	10	PASS
230	-3	90	12	10	PASS
230	+3	180	12	10	PASS
230	-3	180	12	10	PASS
230	+3	270	12	10	PASS
230	-3	270	12	10	PASS

## 14 EMI Scans

### 14.1 EMI Test Set-up

A single-sided 0.062" thick copper-clad FR4 material was placed under the UUT, insulation side up, and with the copper side of the board connected to earth ground at the AC input connector. The evaluation board is placed on top of the ground plane board. Output connector J4 is connected to a high-voltage resistive DC load (500  $\Omega$ ) via a 3.3 mH common-mode choke to avoid the high frequency noise introduced by load wire connections. Auxiliary power to PFS board J3 is supplied by a pair of 9V batteries connected in series, feeding an LM7812 IC regulator, as shown in Figure 79. All interconnections were made as short as possible. See below figure for set-up details.

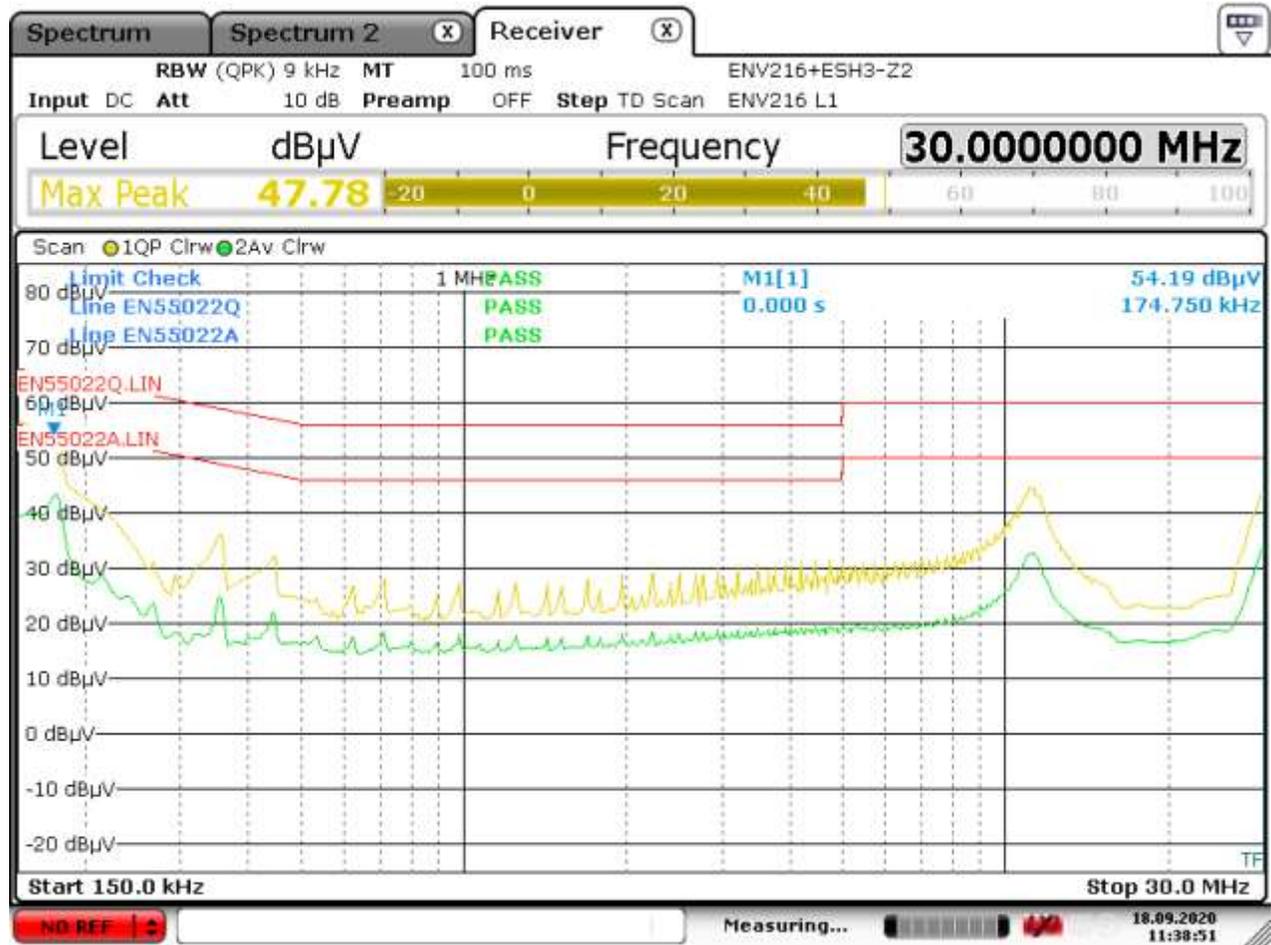


**Figure 79** – 12V Aux Supply for EMI Testing.



**Figure 80** – EMI PFC Test Set-Up.

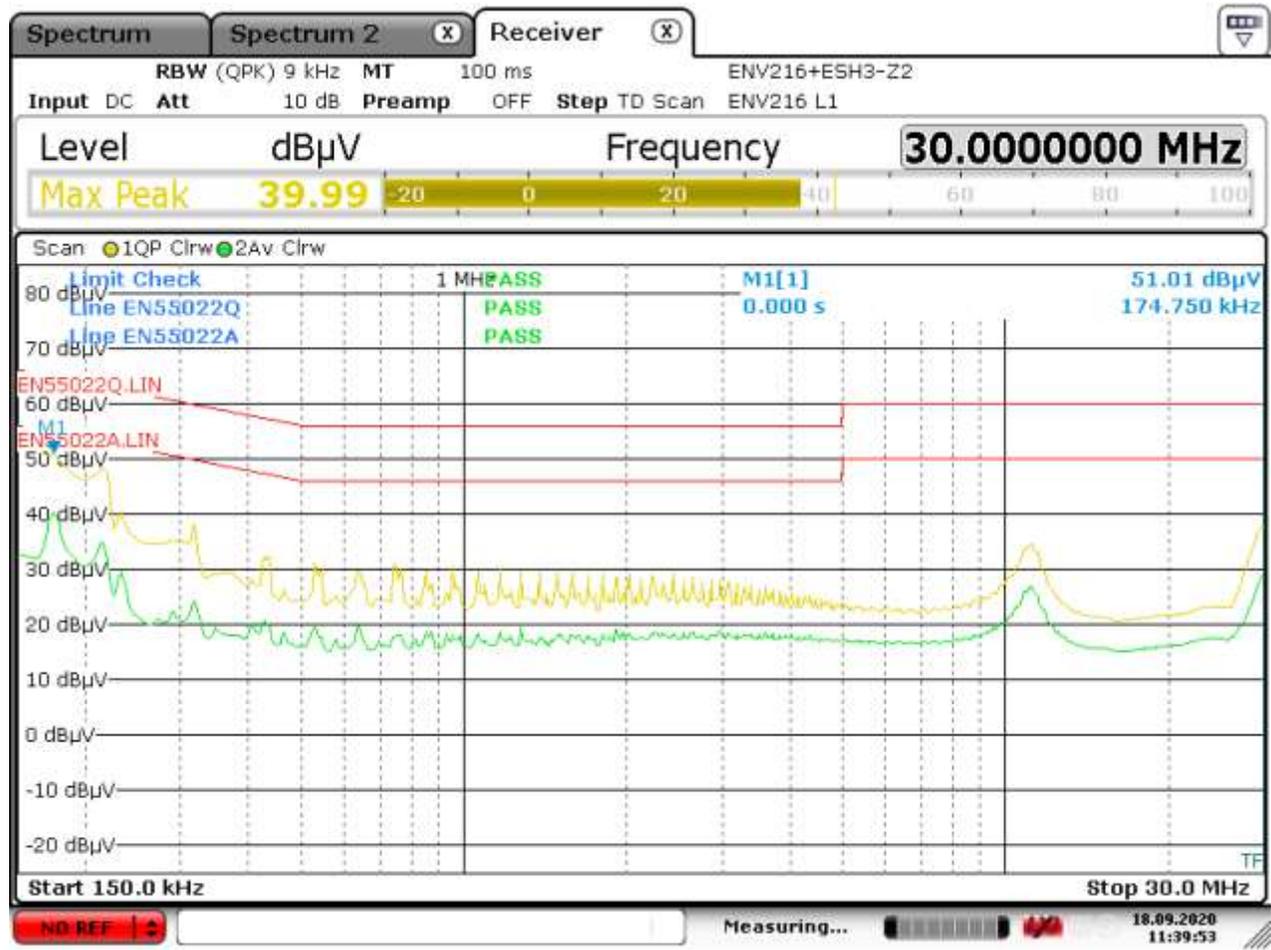
### 14.2 EMI Scans



Date: 18.SEP.2020 11:38:51

Figure 80 – 115 VAC, 100% Load.





Date: 18.SEP.2020 11:39:53

Figure 81 – 230 VAC, 100% Load.

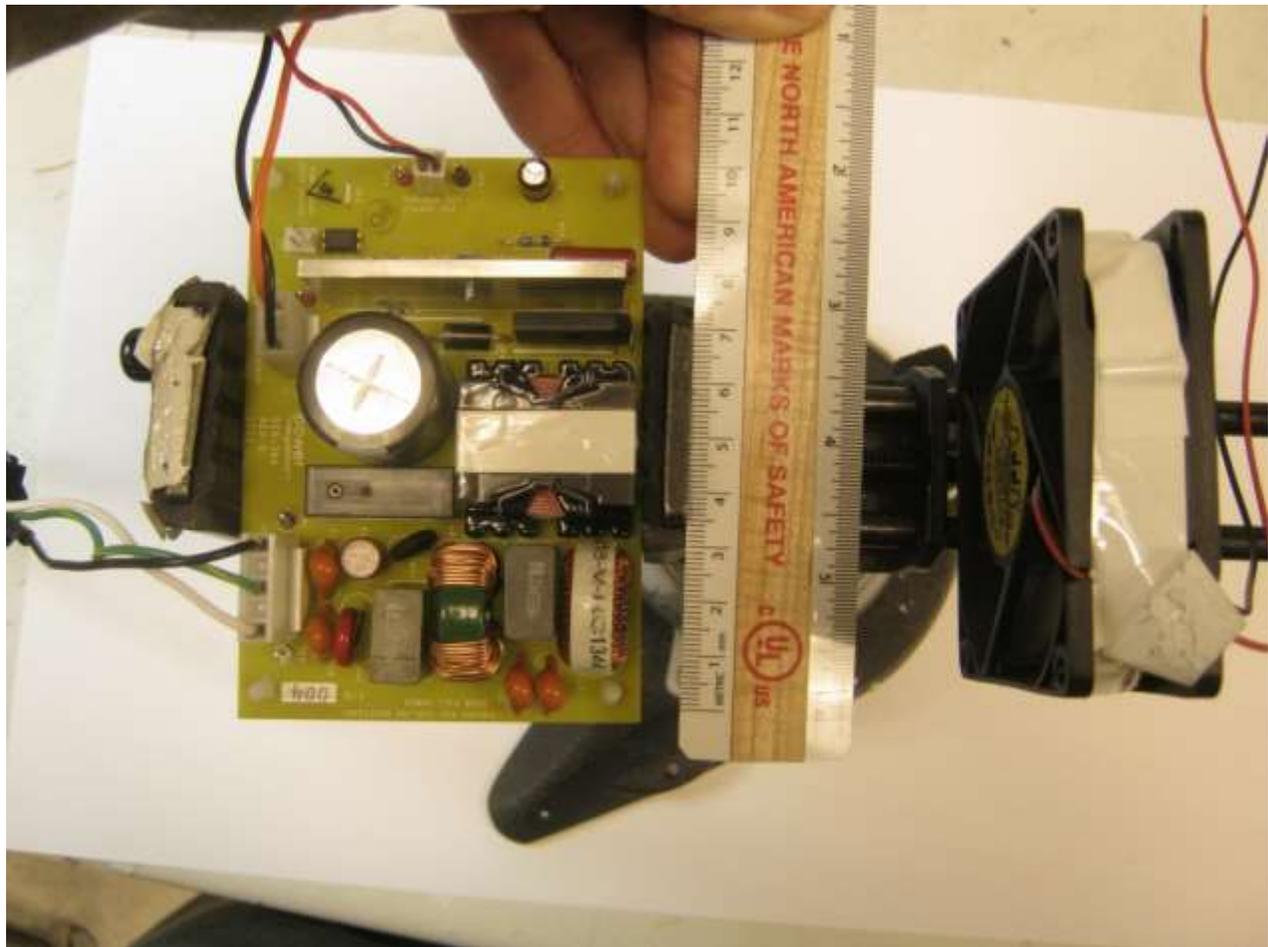
## 15 Appendix A

### 15.1 *Test Set-up for Efficiency Measurement*

The following setup is recommended for system efficiency, PF and THD measurements. Use of high resolution meters is recommended for output current and output voltage measurements. An 80 mm, 12 V DC fan (Adda A08112MS-A70GL) powered by 10 VDC is spaced 70 mm from the board edge for forced air cooling. See figures below for a typical equipment set-up, showing fan spacing and relative placement.



**Figure 82** – Side View of the Test Set-Up for Efficiency, PF and THD Measurements.



**Figure 83** – Top View of the Test Set-Up for Efficiency, PF and THD Measurements.

## 16 Revision History

Date	Author	Revision	Description & changes	Reviewed
13-Oct-20	RH	1.0	Initial Release	Apps & Mktg
05-Nov-20	RH	1.1	Updated Figure 8 and Data.	Apps & Mktg
24-Oct-22	RH	1.2	Added 115 VAC Harmonic Graphs.	Apps & Mktg



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